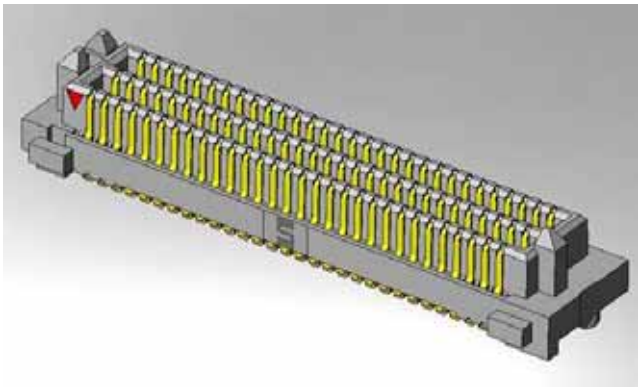
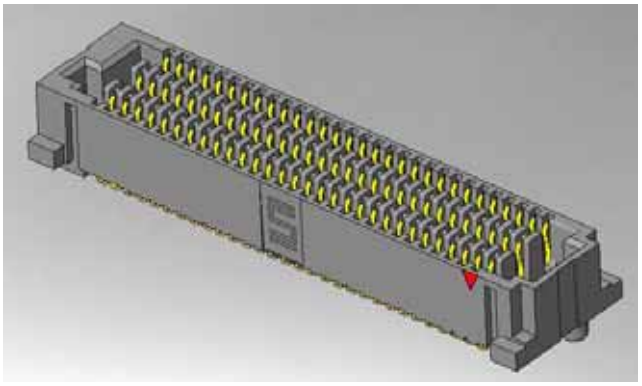
High Speed Characterization Report

SEAM8-XX-S02.0-X-XX-X



Mates with

SEAF8-XX-05.0-X-XX-X



Description:
Open Pin Field Array, 0.8mm Pitch
7mm Stack Height

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Report Revision: 2/8/2013

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table of Contents

Series: SEAM8/SEAF8
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Connector Overview

SEAM8/SEAF8 is a 0.8mm pitch interconnect system for high-speed board-to-board applications. The open pin field design allows for the assignment of both single-ended and differential pair signaling.

The SEAM8/SEAF8 design includes 4, 6, 8 and 10 row open pin field arrays. Pins per row selections are 10, 20, 30, 40 or 50. This report reflects only the hi-speed electrical characteristics specific to a mated 7mm stack height SEAM8/SEAF8 test system.

Connector System Speed Rating

SEAM8/SEAF8 Series, 0.8mm x 0.8mm (0.0315" x 0.0315") pitch interconnect, 7mm Stack Height.

Signaling	Speed Rating
Single-Ended: 1:1 S/G	**12 GHz/ 24Gbps**
Single-Ended: 2:1 S/G	**11 GHz/ 22Gbps**
Differential: Optimal Horizontal	**9 GHz/ 18Gbps**
Differential: Optimal Vertical	**14 GHz/ 28Gbps**
Differential: High Density Vertical	**12.5 GHz/ 25Gbps**

The Speed Rating is based on the -3 dB insertion loss point of the connector system. The -3 dB point can be used to estimate usable system bandwidth in a typical, two-level signaling environment.

To calculate the Speed Rating, the measured -3 dB point is rounded up to the nearest half-GHz level. The up rounding corrects for a portion of the test board's trace loss, since a short length of trace loss is included in the loss data in this report. The resulting loss value is then doubled to determine the approximate maximum data rate in Gigabits per second (Gbps).

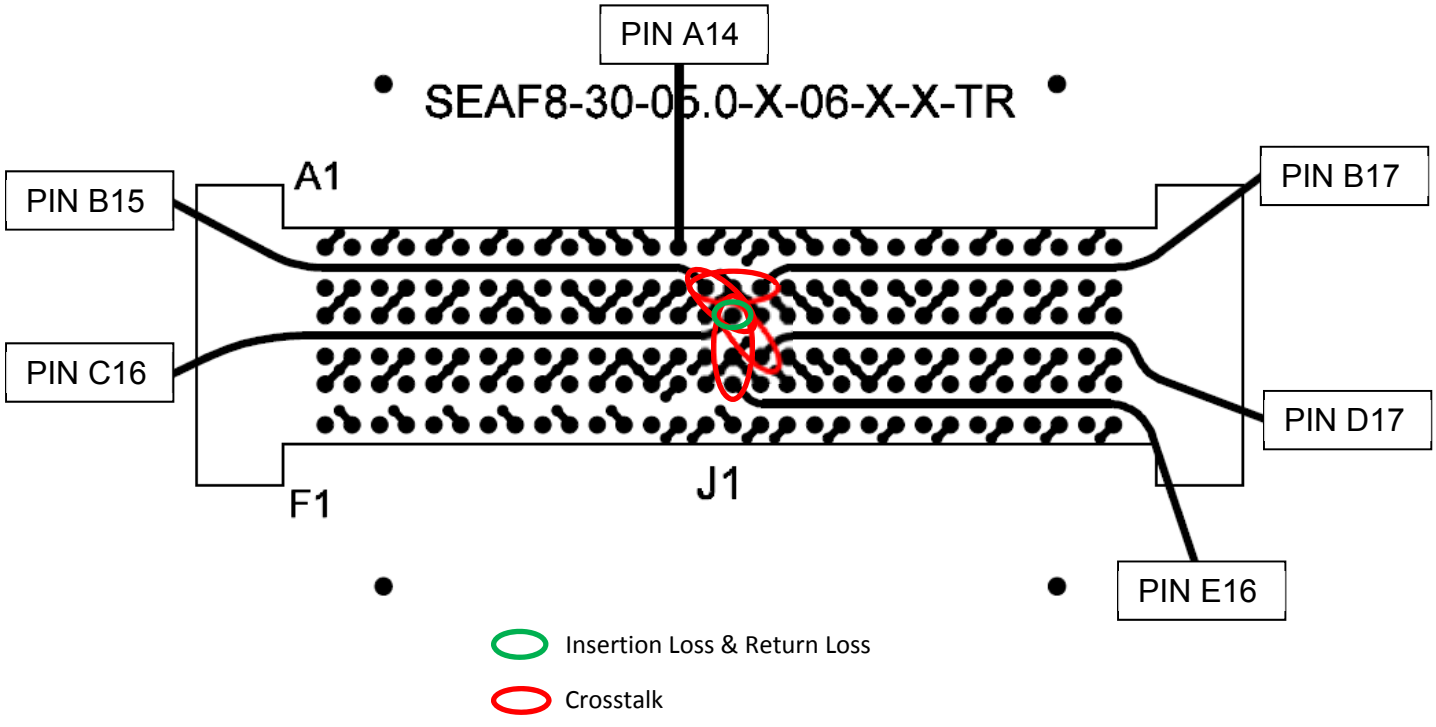
For example, a connector with a -3 dB point of 7.8 GHz would have a Speed Rating of 8 GHz/ 16 Gbps. A connector with a -3 dB point of 7.2 GHz would have a Speed Rating of 7.5 GHz/15 Gbps.

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Frequency Domain Data Summary

Table 1 - Single-Ended 1:1 S/G Pattern Performance			
Test Parameter	**Driver**	**Receiver**	
Insertion Loss	SEAM8_C16	SEAF8_C16	3dB@ 11.7 GHz
Return Loss	SEAM8_C16	SEAM8_C16	>10dB to 7.8 GHz
Near-End Crosstalk	SEAM8_B15	SEAM8_B17	<-20dB to 20.0GHz
	SEAM8_C16	SEAM8_D17	<-20dB to 20.0GHz
	SEAM8_C16	SEAM8_E16	<-20dB to 11.7 GHz
Far-End Crosstalk	SEAM8_C16	SEAF8_B15	<-20dB to 11.1GHz
	SEAM8_C16	SEAF8_D17	<-20dB to 20.0 GHz
	SEAM8_C16	SEAF8_E16	<-20dB to 13.2 GHz

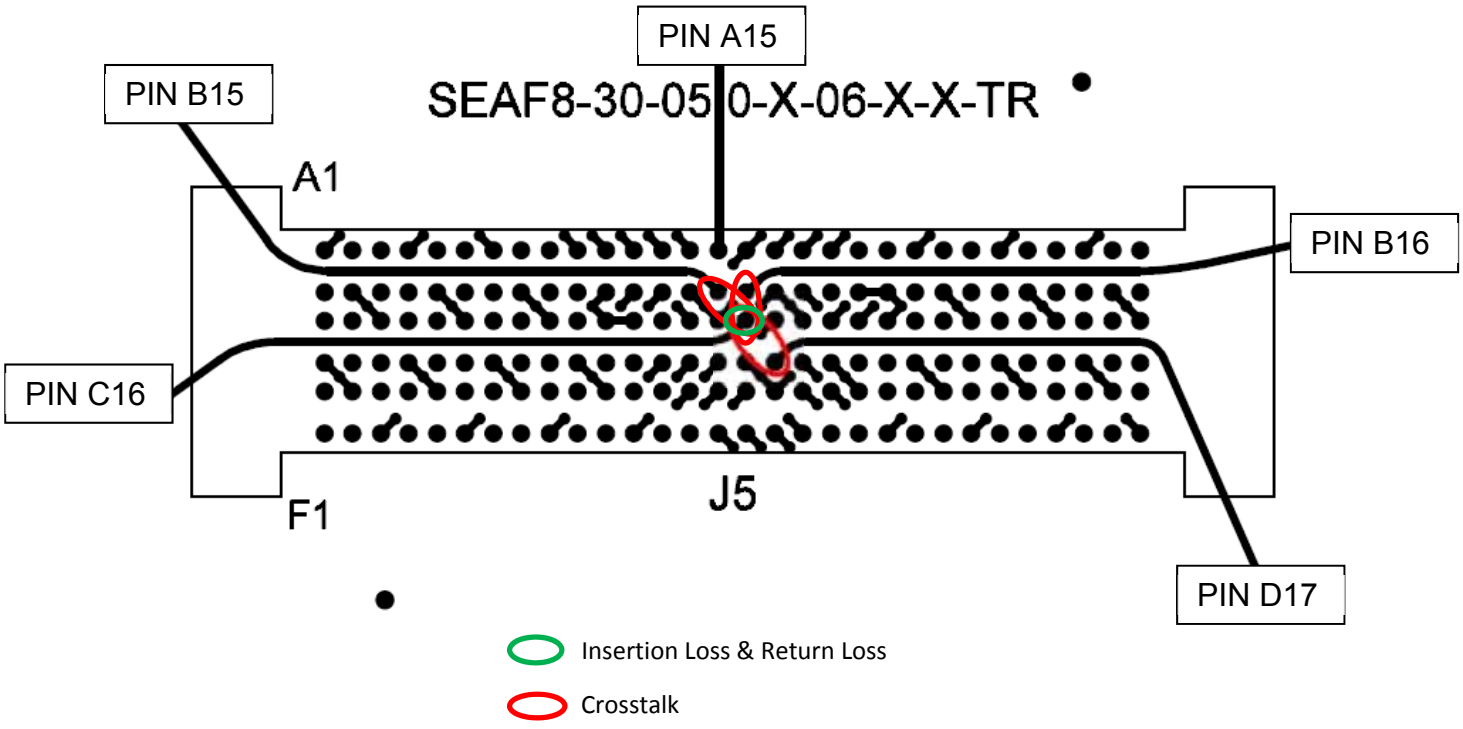
Single-Ended 1:1 S/G Pattern Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 2 - Single-Ended 2:1 S/G Pattern Performance			
Test Parameter	**Driver**	**Receiver**	
Insertion Loss	SEAM8_C16	SEAF8_C16	3dB@ 10.8 GHz
Return Loss	SEAM8_C16	SEAM8_C16	>10dB to 7.6 GHz
Near-End Crosstalk	SEAM8_B15	SEAM8_C16	<-20dB to 10.7 GHz
	SEAM8_B16	SEAM8_C16	<-20dB to 2.8 GHz
	SEAM8_C16	SEAM8_D17	<-20dB to 20.0 GHz
Far-End Crosstalk	SEAM8_C16	SEAF8_B15	<-20dB to 10.4 GHz
	SEAM8_C16	SEAF8_B16	<-20dB to 20.0 GHz
	SEAM8_C16	SEAF8_D17	<-20dB to 20.0 GHz

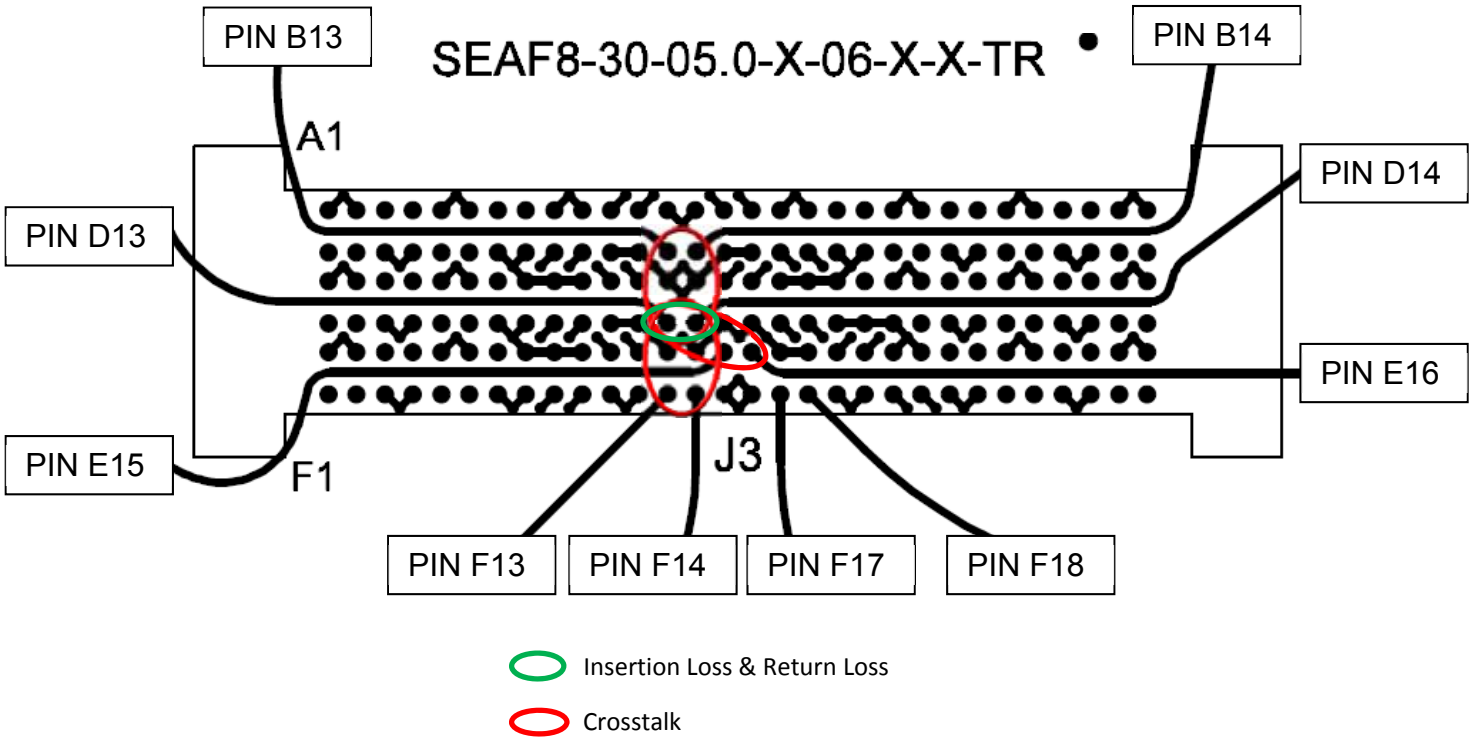
Single-Ended 2:1 S/G Pattern Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 3 - Differential Optimal Horizontal Performance			
Test Parameter	**Driver**	**Receiver**	
Insertion Loss	SEAM8_D13,D14	SEAF8_D13,D14	3dB@ 9.0 GHz
Return Loss	SEAM8_D13,D14	SEAM8_D13,D14	>10dB to 9.3 GHz
Near-End Crosstalk	SEAM8_B13,B14	SEAM8_D13,D14	<-20dB to 8.7 GHz
	SEAM8_D13,D14	SEAM8_E15,E16	<-20dB to 8.7 GHz
	SEAM8_D13,D14	SEAM8_F13,F14	<-20dB to 20.0 GHz
Far-End Crosstalk	SEAM8_D13,D14	SEAF8_B13,B14	<-20dB to 8.5 GHz
	SEAM8_D13,D14	SEAF8_E15,E16	<-20dB to 8.8 GHz
	SEAM8_D13,D14	SEAF8_F13,F14	<-20dB to 20.0 GHz

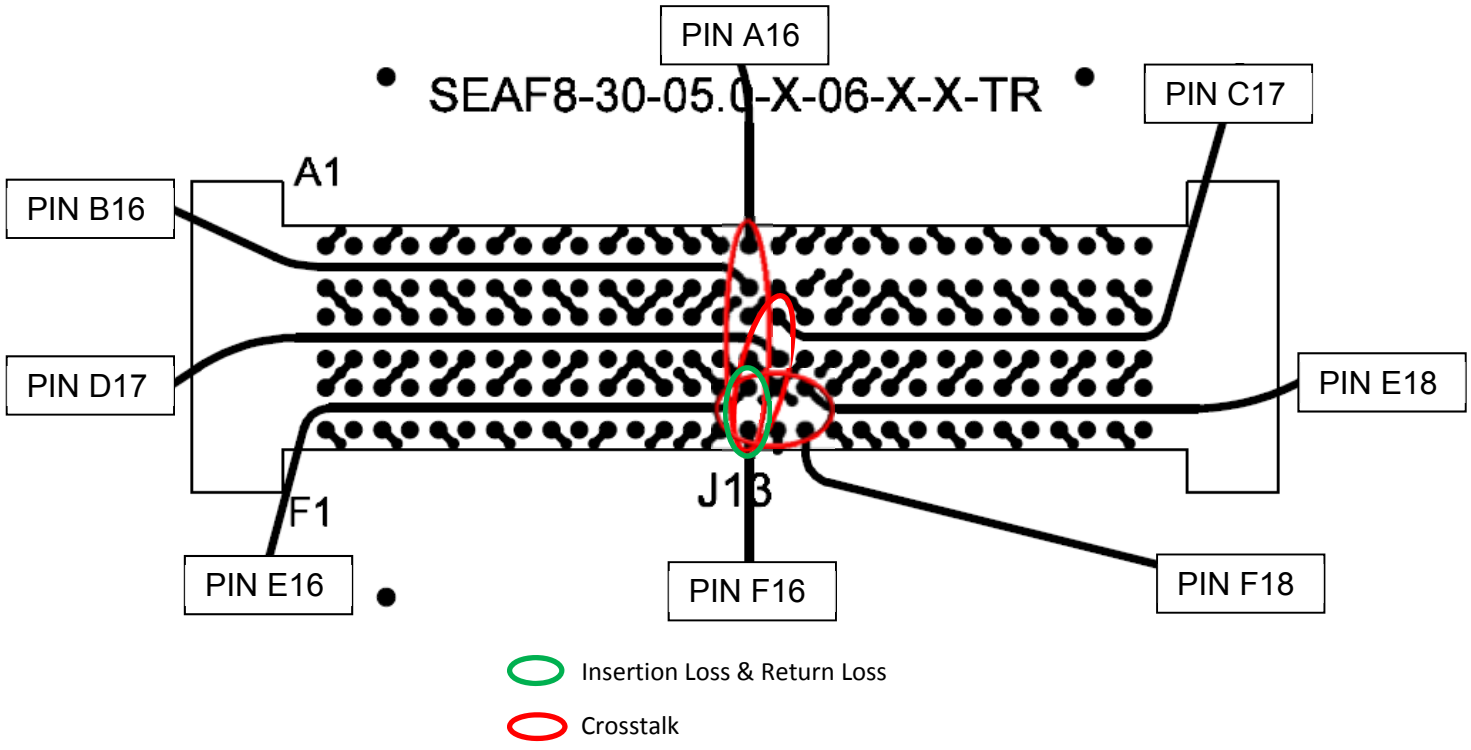
Differential Optimal Horizontal Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 4 - Differential Optimal Vertical Performance			
Test Parameter	**Driver**	**Receiver**	
Insertion Loss	SEAM8_E16,F16	SEAF8_E16,F16	3dB@ 13.7 GHz
Return Loss	SEAM8_E16,F16	SEAM8_E16,F16	>10dB to 8.0 GHz
Near-End Crosstalk	SEAM8_A16,B16	SEAM8_E16,F16	<-20dB to 20.0 GHz
	SEAM8_C17,D17	SEAM8_E16,F16	<-20dB to 12.9 GHz
	SEAM8_E16,F16	SEAM8_E18,F18	<-20dB to 20.0 GHz
Far-End Crosstalk	SEAM8_E16,F16	SEAF8_A16,B16	<-20dB to 20.0 GHz
	SEAM8_E16,F16	SEAF8_C17,D17	<-20dB to 12.7 GHz
	SEAM8_E16,F16	SEAF8_E18,F18	<-20dB to 20.0 GHz

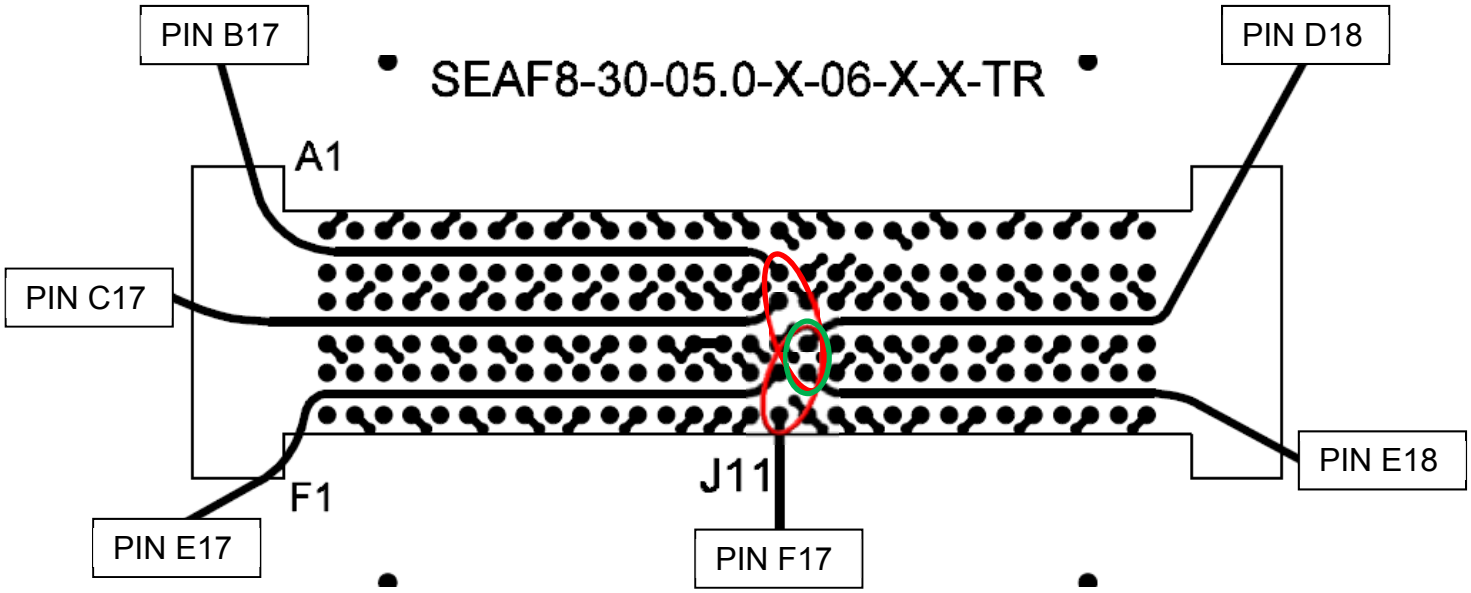
Differential Optimal Vertical Pin Map



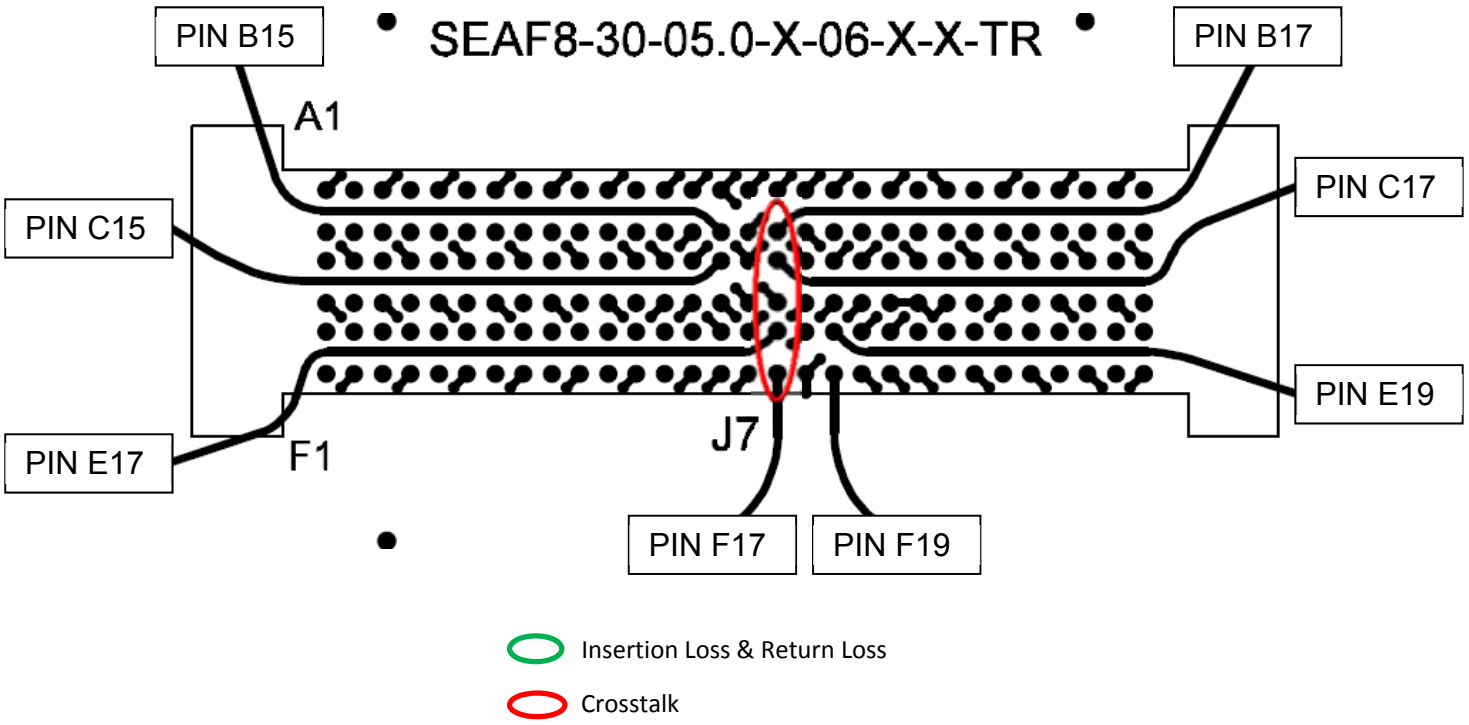
Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 5 - Differential High Density Vertical Performance			
Test Parameter	**Driver**	**Receiver**	
Insertion Loss	SEAM8_D18,E18	SEAF8_D18,E18	3dB@ 12.3 GHz
Return Loss	SEAM8_D18,E18	SEAM8_D18,E18	>10dB to 8.3 GHz
Near-End Crosstalk	SEAM8_B17,C17	SEAM8_D18,E18	<-20dB to 20.0 GHz
	SEAM8_B17,C17	SEAM8_E17,F17	<-20dB to 20.0 GHz
	SEAM8_D18,E18	SEAM8_E17,F17	<-20dB to 13.4 GHz
Far-End Crosstalk	SEAM8_B17,C17	SEAF8_E17,F17	<-20dB to 20.0 GHz
	SEAM8_D18,E18	SEAF8_B17,C17	<-20dB to 20.0 GHz
	SEAM8_D18,E18	SEAF8_E17,F17	<-20dB to 20.0 GHz

Differential High Density Vertical Pin Map



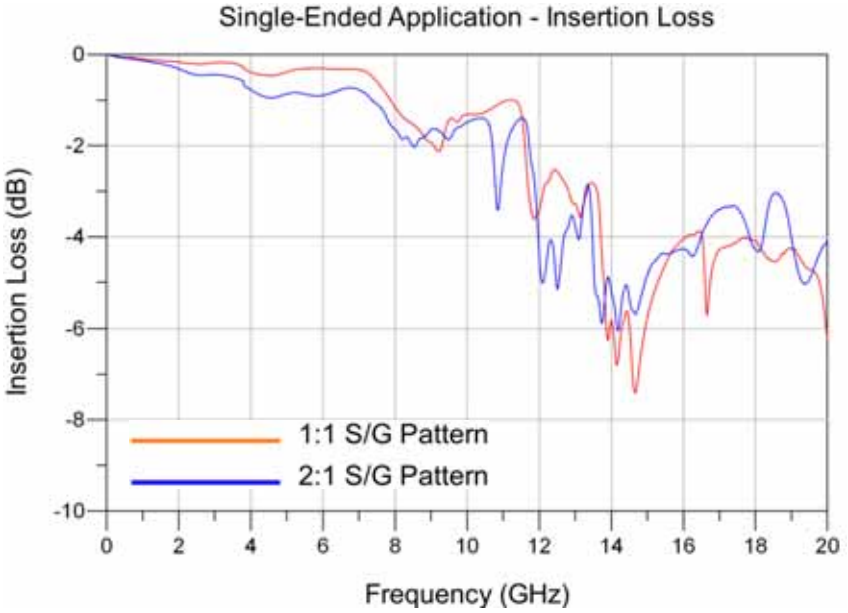
Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

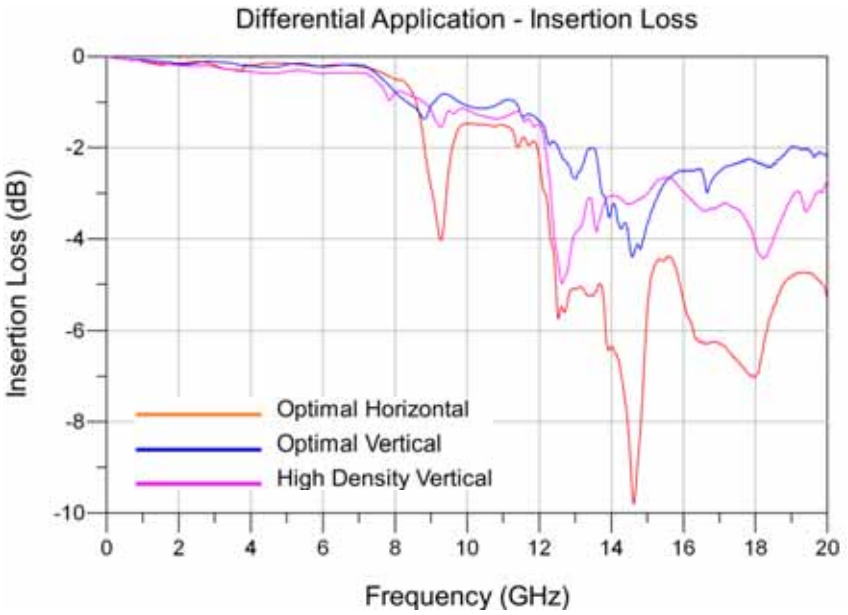


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Bandwidth Charts – Single-Ended & Differential Insertion Loss

SEAM8/SEAF8 Array Series





Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Time Domain Data Summary

Table 6 – Single-End Impedance (Ω) – 1:1 S/G Pattern					
Signal Risetime	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
Maximum Impedance	69.2	60.3	53.6	50.6	50.3
Minimum Impedance	43.6	45.6	46.6	47.9	48.9

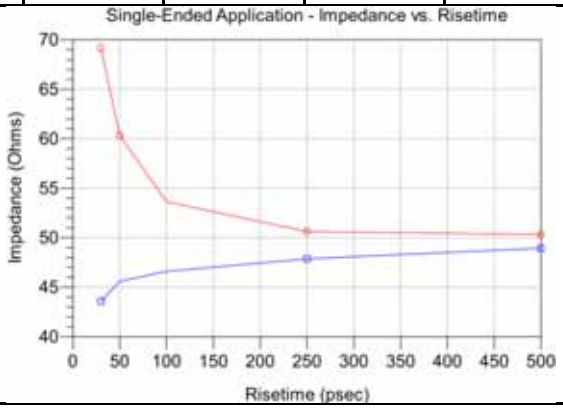
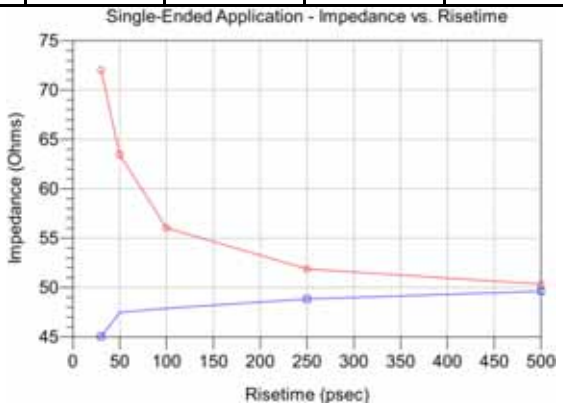


Table 7 – Single-End Impedance (Ω) – 2:1 S/G Pattern					
Signal Risetime	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
Maximum Impedance	72.0	63.4	56.0	51.9	50.3
Minimum Impedance	45.0	47.5	47.9	48.8	49.6



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 8 – Differential Impedance (Ω) – Optimal Horizontal					
Signal Risetime	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
Maximum Impedance	113.3	107.0	105.9	103.0	101.5
Minimum Impedance	77.2	86.8	93.3	96.3	98.7

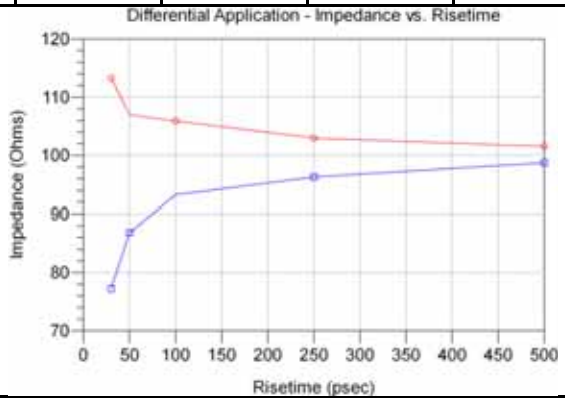
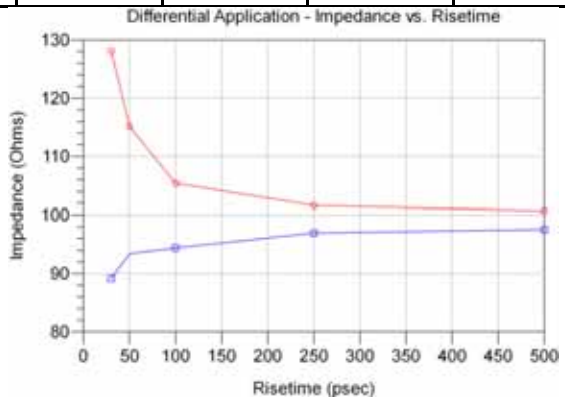
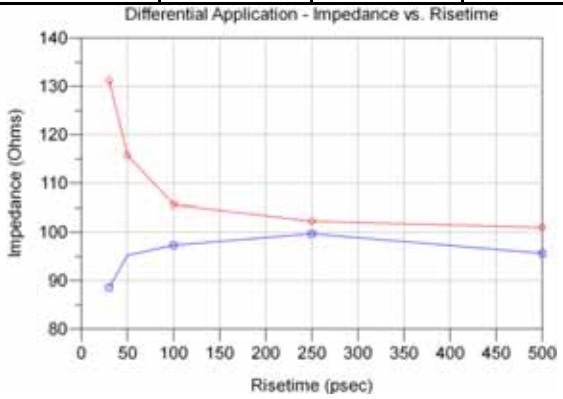


Table 9 – Differential Impedance (Ω) – Optimal Vertical					
Signal Risetime	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
Maximum Impedance	128.2	115.1	105.4	101.6	100.7
Minimum Impedance	89.2	93.4	94.4	96.9	97.6



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

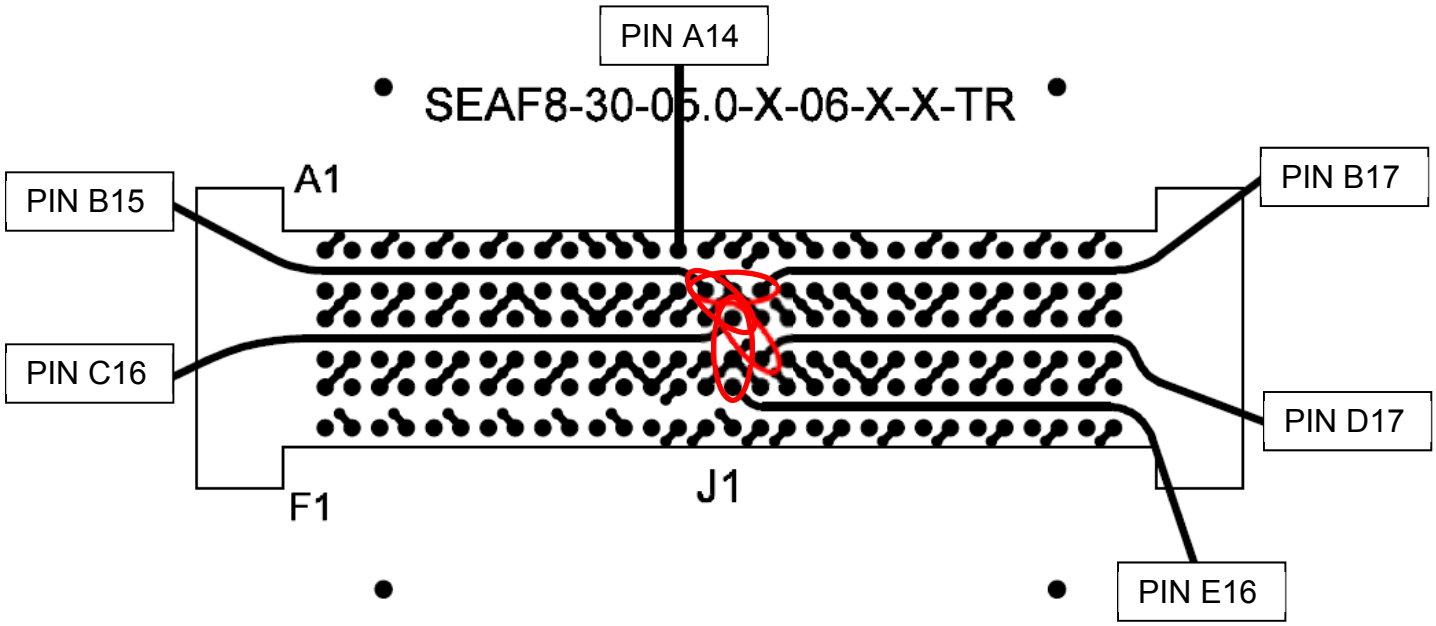
Table 10 – Differential Impedance (Ω) – High Density Vertical					
Signal Risetime	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
Maximum Impedance	131.2	115.7	105.6	102.3	101.0
Minimum Impedance	88.6	95.2	97.3	99.7	95.6



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 11 - Single-Ended Crosstalk (%) – 1:1 S/G Pattern							
Input(tr)	**Driver**	**Receiver**	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
NEXT	SEAM8_B15	SEAM8_B17	0.81	0.71	0.48	0.22	0.12
	SEAM8_C16	SEAM8_D17	2.23	2.06	1.47	0.69	0.36
	SEAM8_C16	SEAM8_E16	1.25	0.96	0.46	0.22	0.15
FEXT	SEAM8_C16	SEAF8_B15	2.79	2.15	1.14	0.46	0.23
	SEAM8_C16	SEAF8_D17	0.92	0.77	0.47	0.20	<0.1
	SEAM8_C16	SEAF8_E16	1.44	1.10	0.56	0.21	0.12

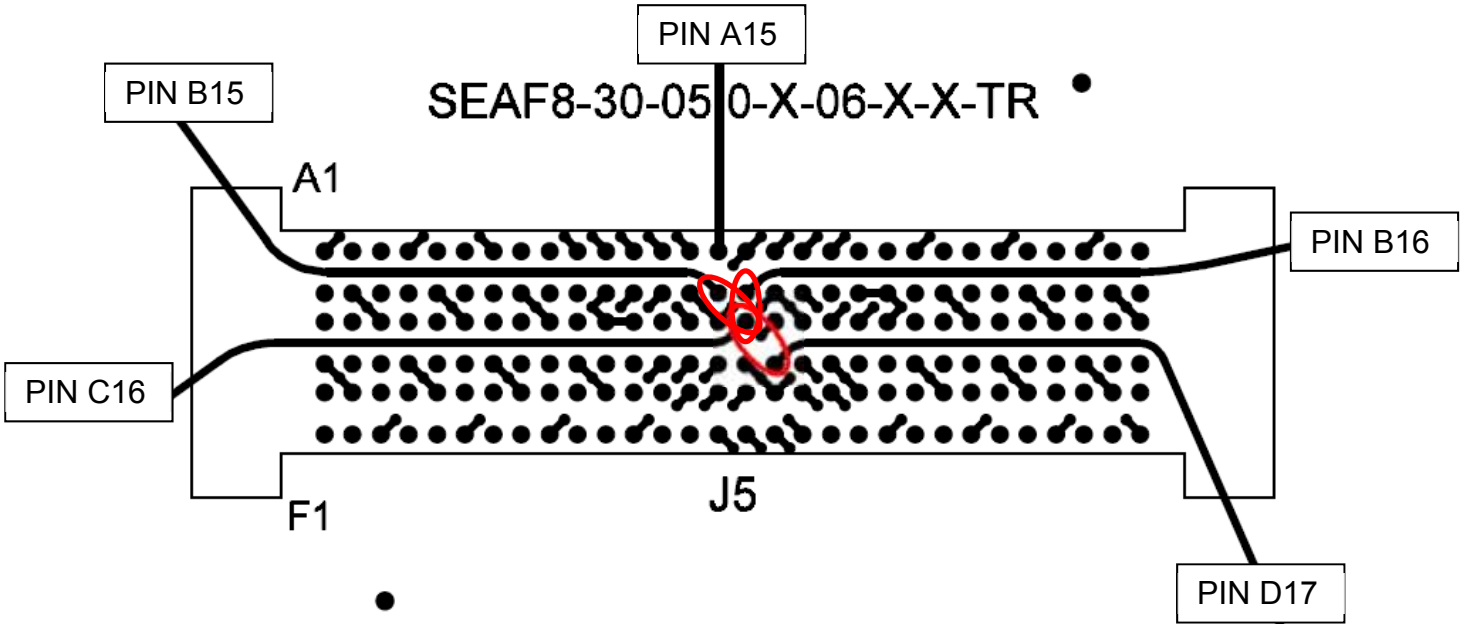
Single-Ended 1:1 S/G Pattern Crosstalk Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 12 - Single-Ended Crosstalk (%) – 2:1 S/G Pattern							
Input(tr)	**Driver**	**Receiver**	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
NEXT	SEAM8_B15	SEAM8_C16	3.10	2.81	2.18	1.16	0.64
	SEAM8_B16	SEAM8_C16	8.28	7.46	5.68	2.85	1.47
	SEAM8_C16	SEAM8_D17	3.07	2.85	2.15	1.11	0.60
FEXT	SEAM8_C16	SEAF8_B15	4.03	3.20	2.03	0.95	0.49
	SEAM8_C16	SEAF8_B16	3.96	3.07	1.98	0.90	0.46
	SEAM8_C16	SEAF8_D17	1.99	1.79	1.28	0.61	0.31

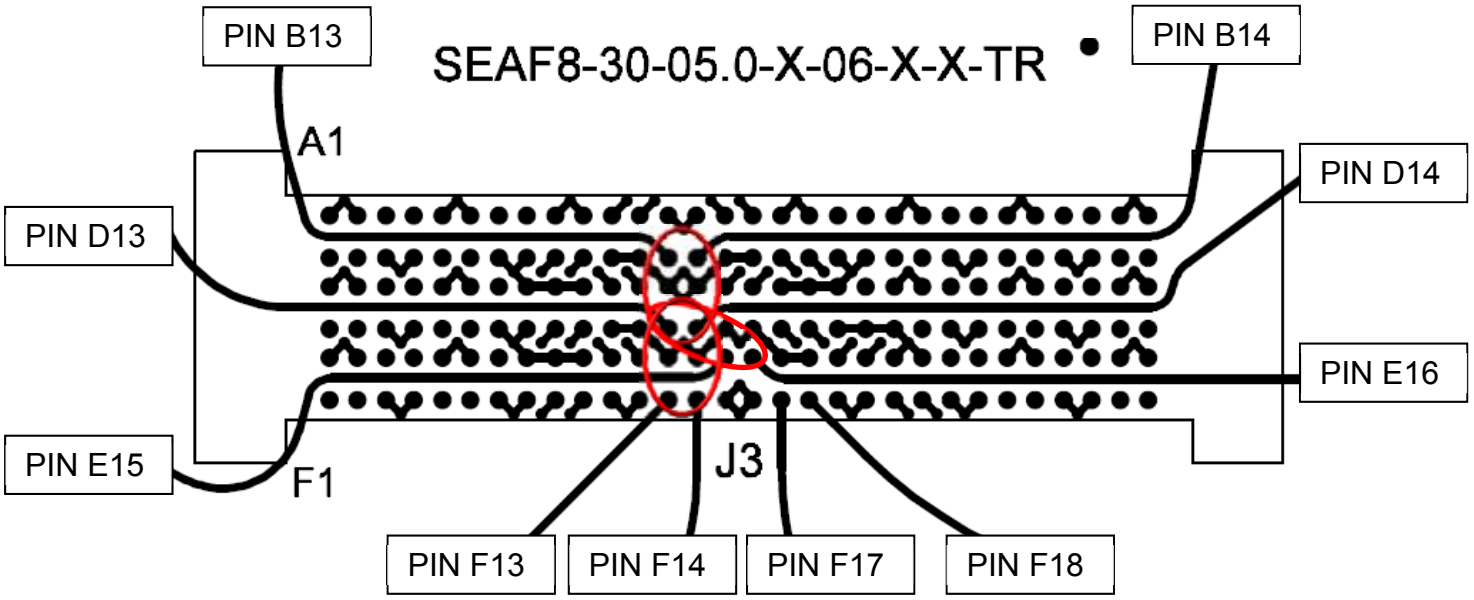
Single-Ended 2:1 S/G Pattern Crosstalk Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 13 - Differential Crosstalk (%) – Optimal Horizontal							
Input(tr)	**Driver**	**Receiver**	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
NEXT	SEAM8_B13,B14	SEAM8_D13,D14	0.73	0.66	0.44	0.20	0.15
	SEAM8_D13,D14	SEAM8_E15,E16	1.51	1.42	1.02	0.44	<0.1
	SEAM8_D13,D14	SEAM8_F13,F14	<0.1	<0.1	<0.1	<0.1	<0.1
FEXT	SEAM8_D13,D14	SEAF8_B13,B14	3.16	2.27	0.99	0.34	0.21
	SEAM8_D13,D14	SEAF8_E15,E16	2.51	1.85	0.83	0.29	0.20
	SEAM8_D13,D14	SEAF8_F13,F14	0.11	<0.1	<0.1	<0.1	<0.1

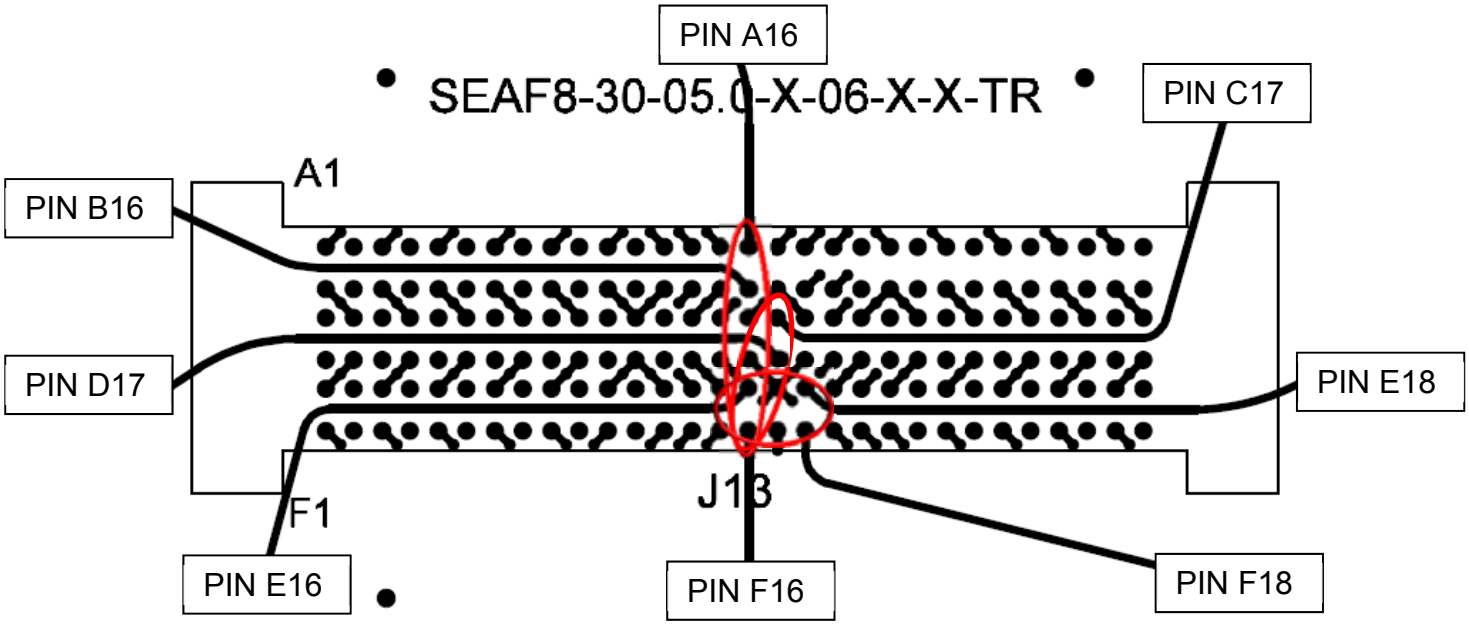
Differential Optimal Horizontal Crosstalk Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 14 - Differential Crosstalk (%) – Optimal Vertical							
Input(tr)	**Driver**	**Receiver**	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
NEXT	SEAM8_A16,B16	SEAM8_E16,F16	0.16	<0.1	<0.1	<0.1	<0.1
	SEAM8_C17,D17	SEAM8_E16,F16	0.81	0.73	0.53	0.25	0.25
	SEAM8_E16,F16	SEAM8_E18,F18	1.04	0.85	0.55	0.25	0.12
FEXT	SEAM8_E16,F16	SEAF8_A16,B16	0.20	0.12	<0.1	<0.1	<0.1
	SEAM8_E16,F16	SEAF8_C17,D17	1.53	1.13	0.53	0.20	0.11
	SEAM8_E16,F16	SEAF8_E18,F18	0.82	0.51	0.25	<0.1	<0.1

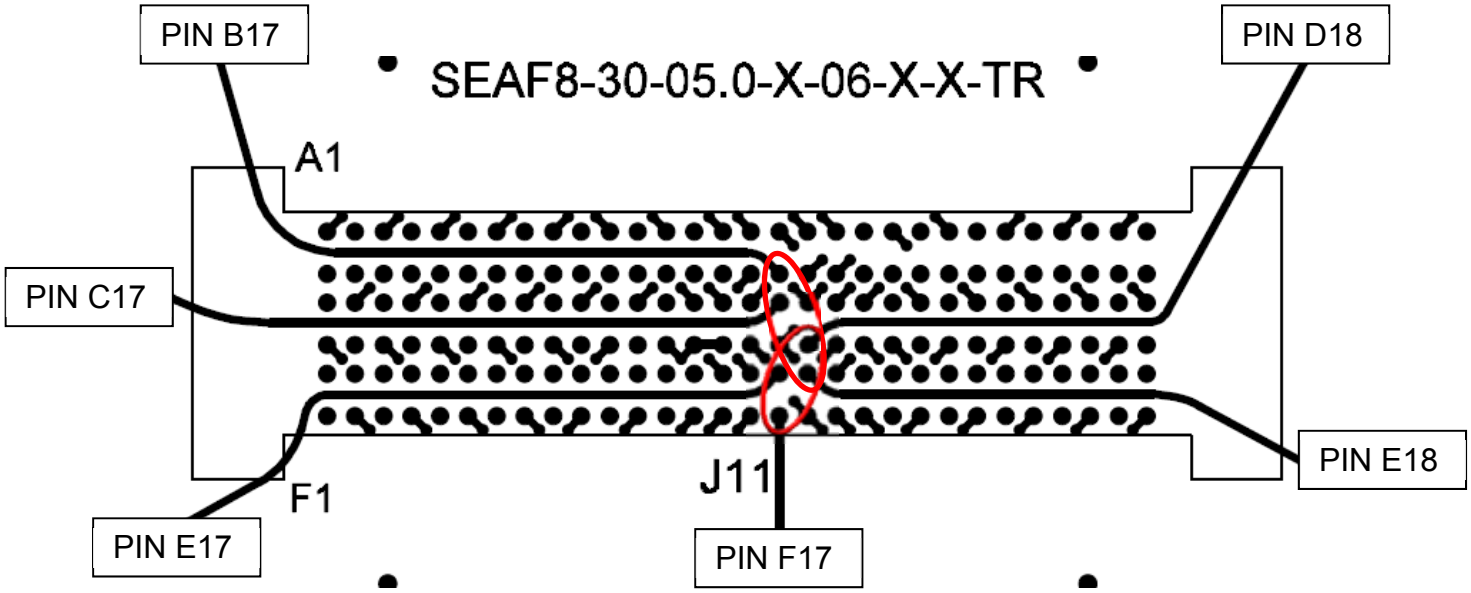
Differential Optimal Vertical Crosstalk Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Table 15 - Differential Crosstalk (%) – High Density Vertical							
Input(tr)	**Driver**	**Receiver**	**30 ps**	**50 ps**	**100 ps**	**250 ps**	**500 ps**
NEXT	SEAM8_B17,C17	SEAM8_D18,E18	1.21	1.09	0.76	0.36	<0.1
	SEAM8_B17,C17	SEAM8_E17,F17	0.17	0.12	0.10	<0.1	<0.1
	SEAM8_D18,E18	SEAM8_E17,F17	4.05	3.47	2.84	1.42	0.65
FEXT	SEAM8_B17,C17	SEAF8_E17,F17	0.16	0.12	<0.1	<0.1	<0.1
	SEAM8_D18,E18	SEAF8_B17,C17	0.37	0.17	<0.1	<0.1	<0.1
	SEAM8_D18,E18	SEAF8_E17,F17	1.23	0.87	0.50	0.22	<0.1

Differential High Density Vertical Crosstalk Pin Map



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

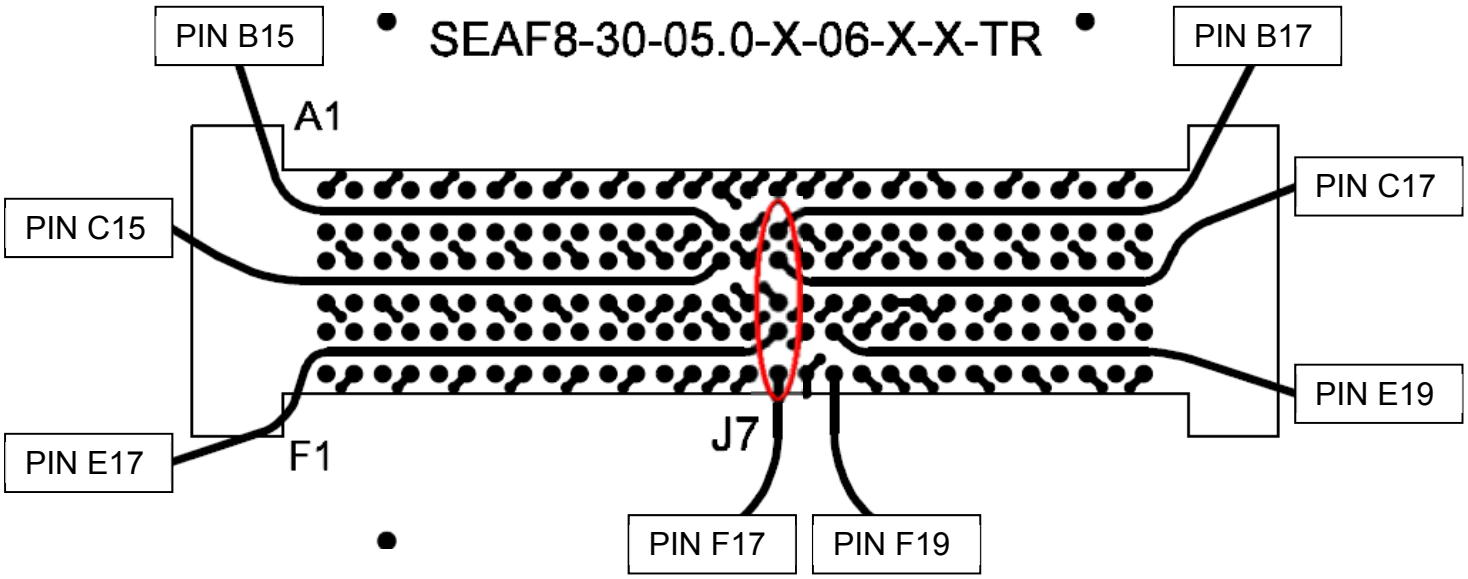


Table 16 - Propagation Delay (Mated Connector)	
Single-Ended: 1:1 S/G	50 ps
Single-Ended: 2:1 S/G	52 ps
Differential: Optimal Horizontal	46 ps
Differential: Optimal Vertical	49 ps
Differential: High Density Vertical	49 ps

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Characterization Details

This report presents data that characterizes the signal integrity response of a connector pair in a controlled printed circuit board (PCB) environment. All efforts are made to reveal typical best-case responses inherent to the system under test (SUT).

In this report, the SUT includes the connector pair and footprint effects on a typical multi-layer PCB. PCB effects (trace loss) are de-embedded from test data. Board related effects, such as pad-to-ground capacitance, are included in the data presented in this report.

Additionally, intermediate test signal connections can mask the connector's true performance. Such connection effects are minimized by using high performance test cables and adapters. Where appropriate, calibration and de-embedding routines are also used to reduce residual effects.

Differential and Single-Ended Data

Most Samtec connectors can be used successfully in both differential and single-ended applications. However, electrical performance will differ depending on the signal drive type. In this report, data is presented for both differential and single-ended drive scenarios.

Connector Signal to Ground Ratio

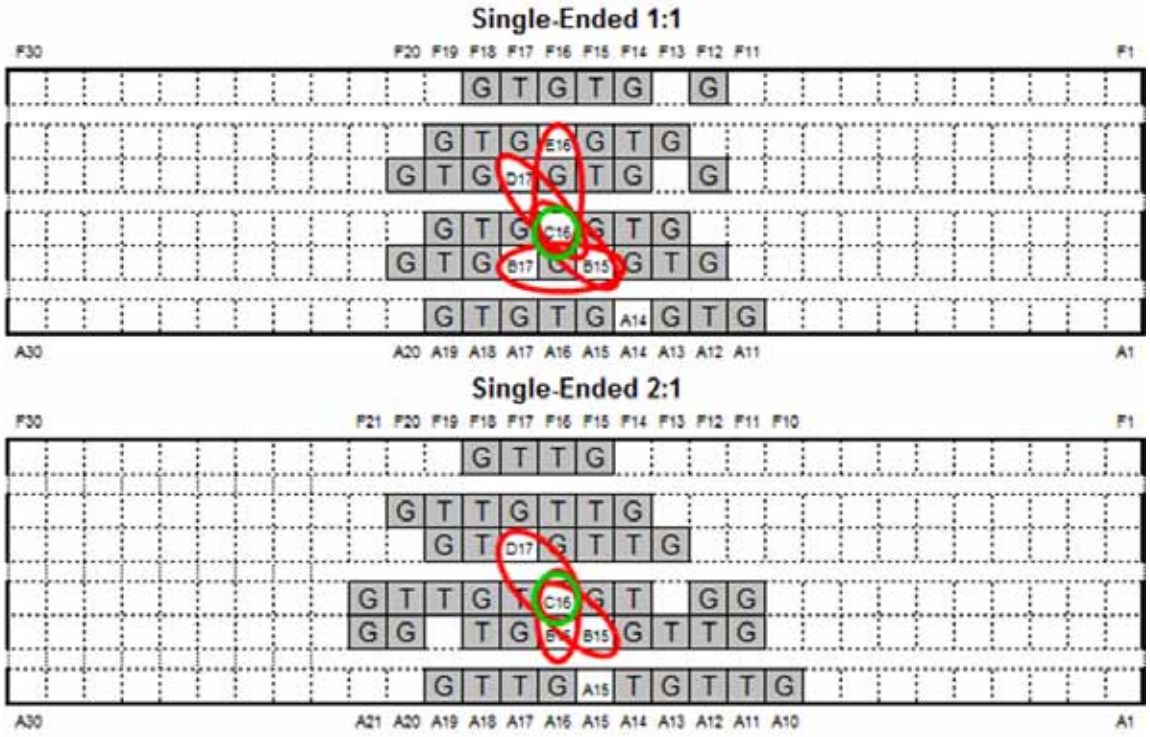
Samtec connectors are most often designed for generic applications and can be implemented using various signal and ground pin assignments. In high-speed systems, provisions must be made in the interconnect for signal return currents. Such paths are often referred to as "ground". In some connectors, a ground plane or blade, or an outer shield, is used as the signal return, while in others, connector pins are used as signal returns. Various combinations of signal pins, ground blades, and shields can also be utilized. Electrical performance can vary significantly depending upon the number and location of ground pins.

In general, the more pins dedicated to ground, the better electrical performance will be. However, dedicating pins to ground reduces signal density of a connector. Therefore, care must be taken when choosing signal/ground ratios in cost or density-sensitive applications.

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

For this connector, the following array configurations are evaluated:

	Open pin field	G	Grounded pin field
	Signal pin field	T	50 ohm termination field



Single-Ended Impedance (denoted by green circles):

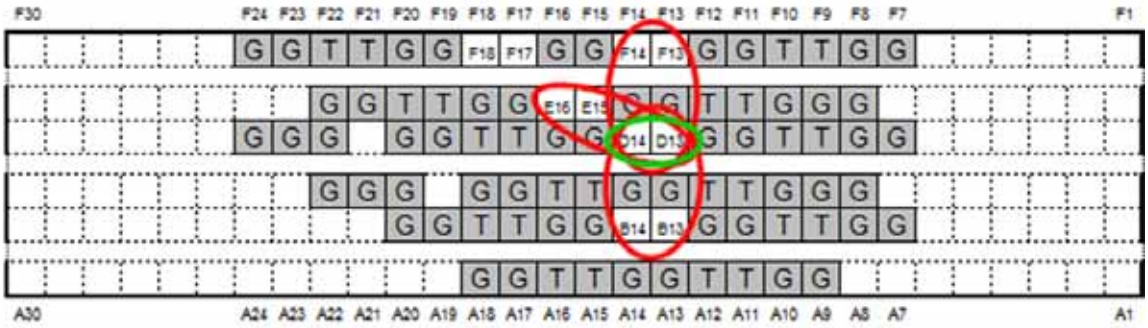
- 1:1 S/G ratio
- 2:1 S/G ratio

Single-Ended Crosstalk (denoted by red circles):

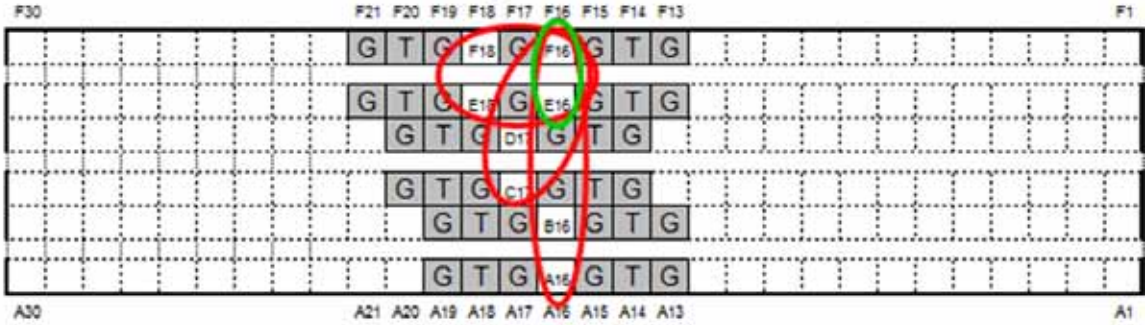
- 1:1 S/G ratio
- 2:1 S/G ratio

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

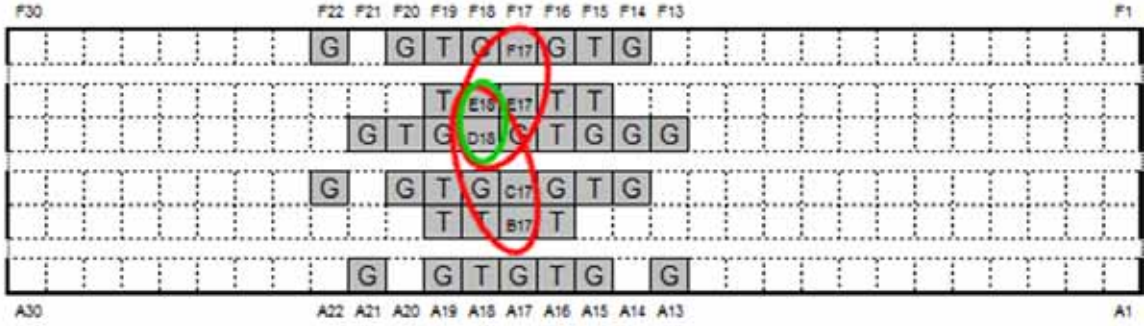
Optimal Horizontal



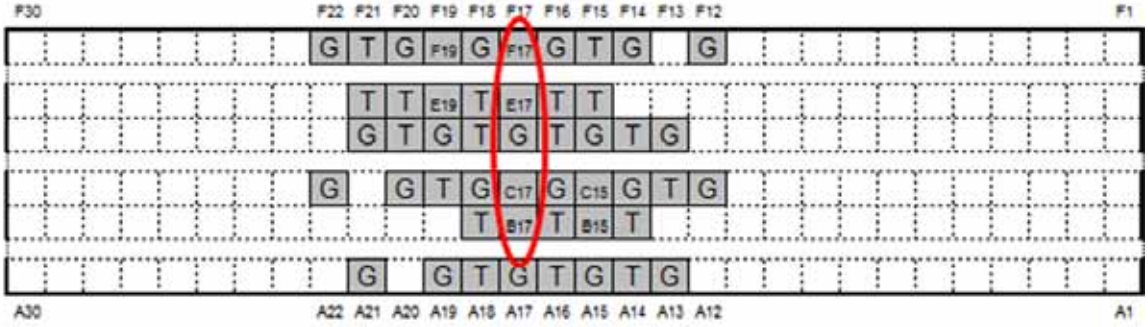
Optimal Vertical



High Density Vertical



High Density Vertical - continue



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential Impedance (denoted by green circles)**:**

- Optimal Horizontal
- Optimal Vertical
- High Density Vertical

Differential Crosstalk (denoted by red circles)**:**

- Optimal Horizontal
- Optimal Vertical
- High Density Vertical

Only one single-ended signal or differential pair was driven for crosstalk measurements.

Other configurations can be evaluated upon request. Please contact sig@samtec.com for more information.

In a real system environment, active signals might be located at the outer edges of the signal contacts of concern, as opposed to the ground signals utilized in laboratory testing. For example, in a single-ended system, a pin-out of "SSSS", or four adjacent single ended signals might be encountered as opposed to the "GSG" and "GSSG" configurations tested in the laboratory. Electrical characteristics in such applications could vary slightly from laboratory results. However, in most applications, performance can safely be considered equivalent.

Signal Edge Speed (Rise Time):
In pulse signaling applications, the perceived performance of the interconnect can vary significantly depending on the edge rate or rise time of the exciting signal. For this report, the fastest rise time used was 30 ps. Generally, this should demonstrate worst-case performance.

In many systems, the signal edge rate will be significantly slower at the connector than at the driver launch point. To estimate interconnect performance at other edge rates, data is provided for several rise times between 30ps and 500ps.

For this report, measured rise times were at 10%-90% signal levels.

Frequency Domain Data
Frequency Domain parameters are helpful in evaluating the connector system's signal loss and crosstalk characteristics across a range of sinusoidal frequencies. In this report, parameters presented in the Frequency Domain are Insertion Loss, Return Loss, and Near-End and Far-End Crosstalk. Other parameters or formats, such as VSWR or S-Parameters, may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Frequency performance characteristics for the SUT are generated directly from network analyzer measurements.

Time Domain Data
Time Domain parameters indicate Impedance mismatch versus length, signal propagation time, and crosstalk in a pulsed signal environment. The measured S-Parameters from the network analyzer are post-processed using Agilent Advanced Design System to obtain the time domain response. Time Domain procedure is provided in Appendix E of this report. Parameters or formats not included in this report may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

In this report, propagation delay is defined as the signal propagation time through the connector and connector footprint. It includes 10 mils of PCB trace on each end of the connector. Delay is measured at 100 picoseconds signal rise-time. Delay is calculated as the difference in time measured between the 50% amplitude levels of the input and output pulses.

Crosstalk or coupled noise data is provided for various signal configurations. All measurements are single disturber. Crosstalk is calculated as a ratio of the input line voltage to the coupled line voltage. The input line is sometimes described as the active or drive line. The coupled line is sometimes described as the quiet or victim line. Crosstalk ratio is tabulated in this report as a percentage. Measurements are made at both the near-end and far-end of the SUT.

Data for other configurations may be available. Please contact our Signal Integrity Group at sig@samtec.com for further information.

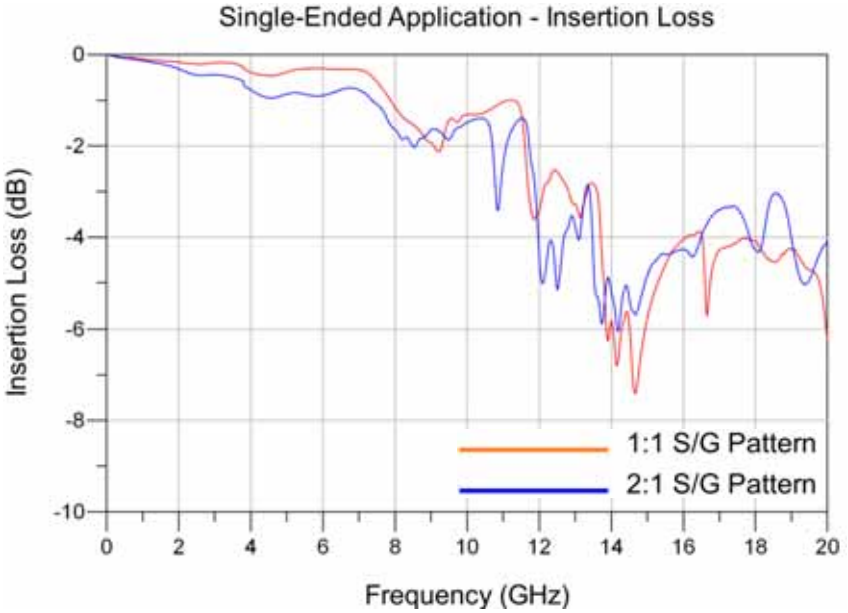
As a rule of thumb, 10% crosstalk levels are often used as a general first pass limit for determining acceptable interconnect performance. However, modern system crosstalk tolerance can vary greatly. For advice on connector suitability for specific applications, please contact our Signal Integrity Group at sig@samtec.com.

Additional information concerning test conditions and procedures is located in the appendices of this report. Further information may be obtained by contacting our Signal Integrity Group at sig@samtec.com.

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Appendix A – Frequency Domain Response Graphs

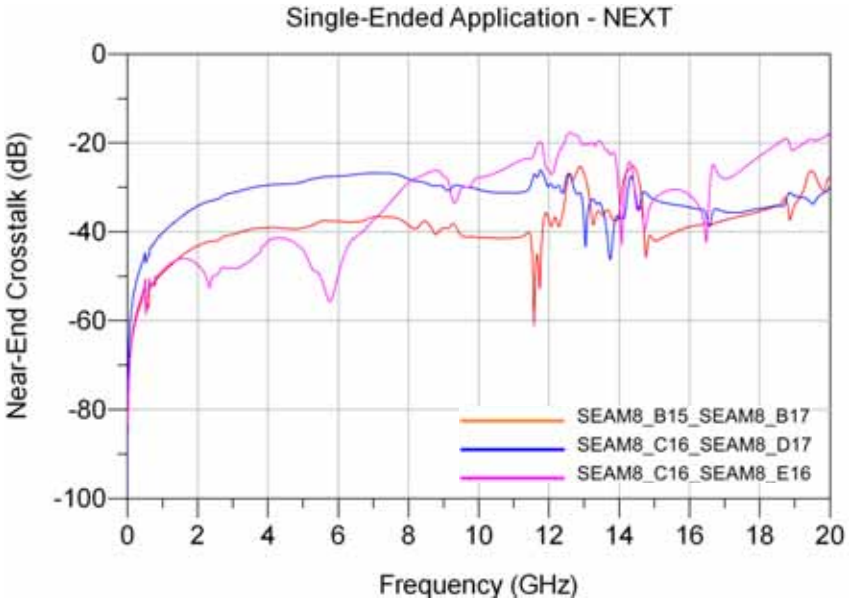
Single-Ended Application – Insertion Loss



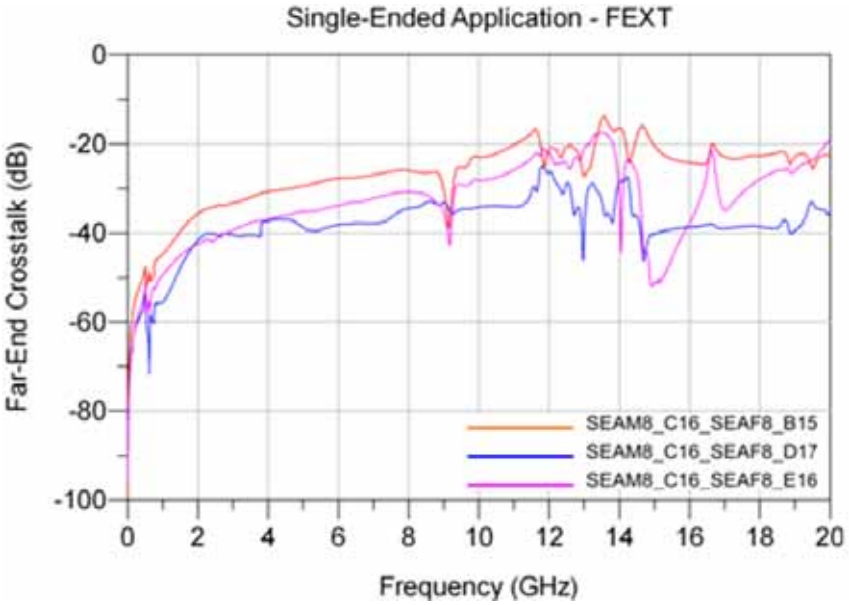
Single-Ended Application – Return Loss

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 1:1 S/G Pattern Application – NEXT

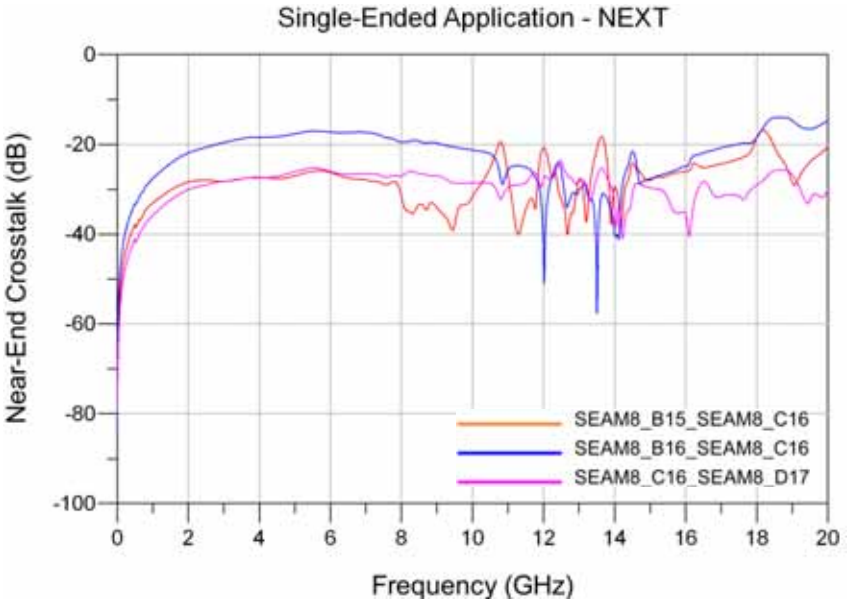


Single-Ended 1:1 S/G Pattern Application – FEXT

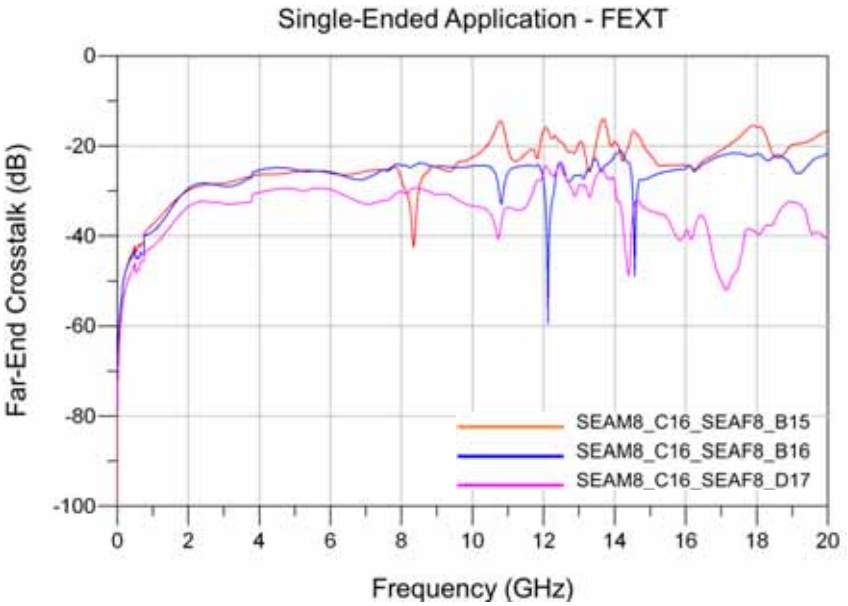


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 2:1 S/G Pattern Application – NEXT

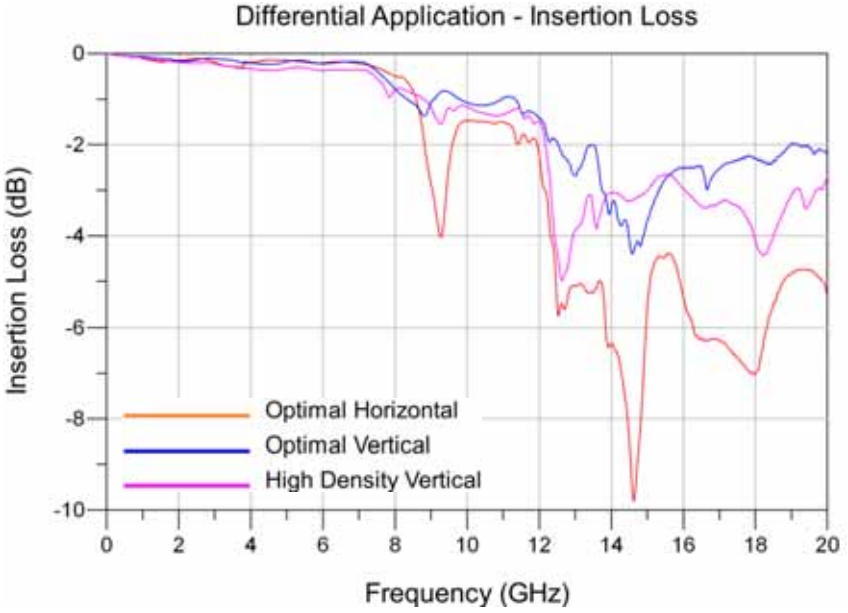


Single-Ended 2:1 S/G Pattern Application – FEXT

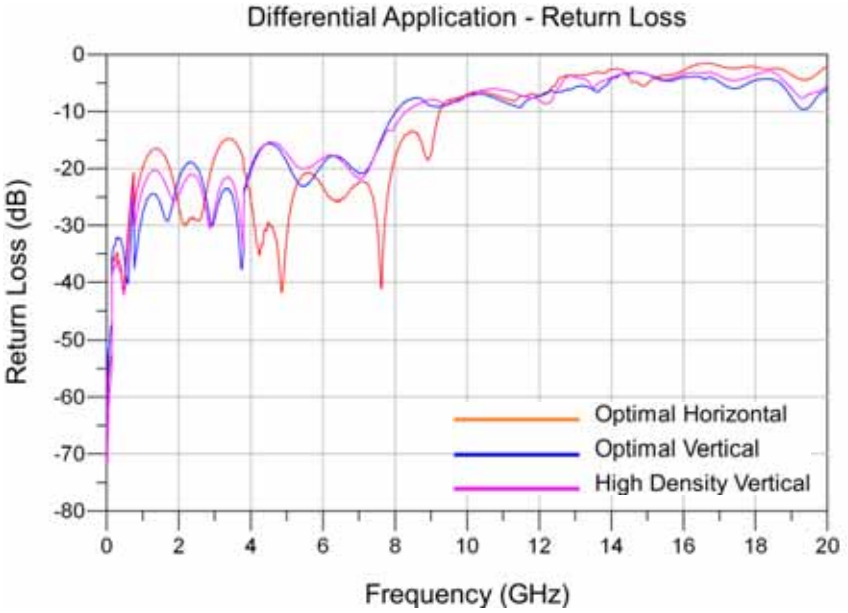


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential Application – Insertion Loss

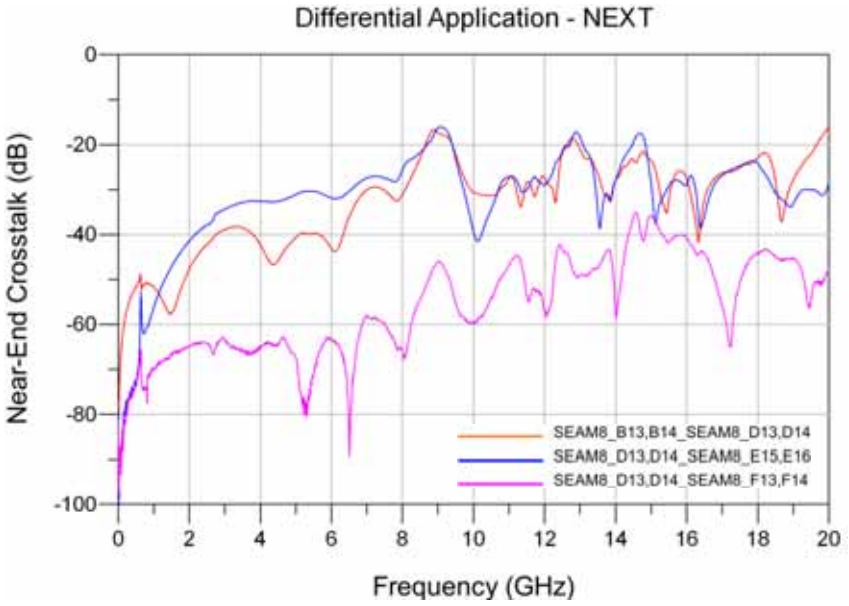


Differential Application – Return Loss

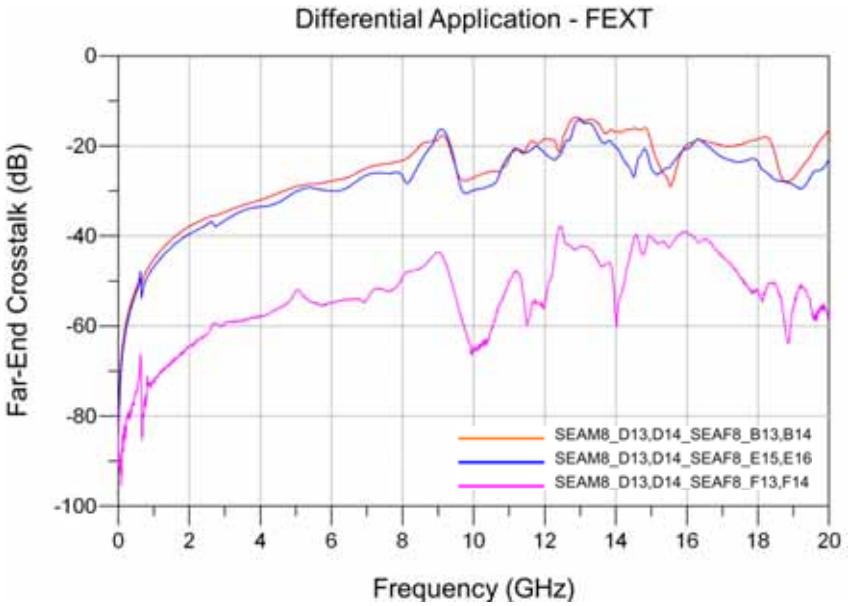


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential Optimal Horizontal Application – NEXT

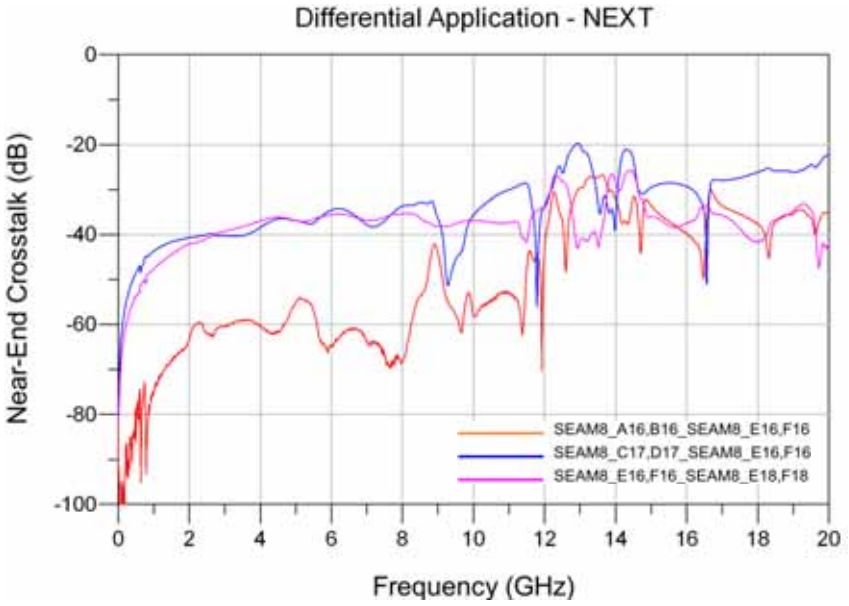


Differential Optimal Horizontal Application – FEXT

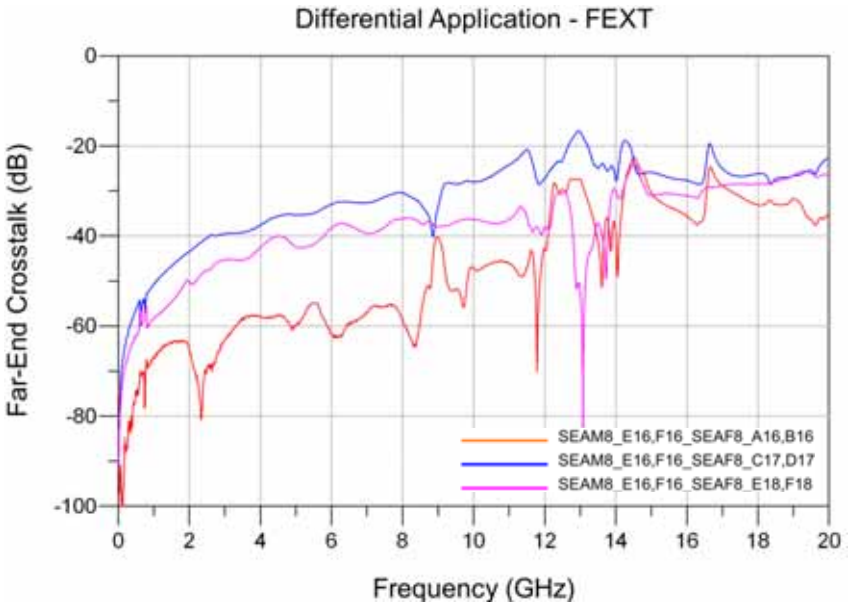


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential Optimal Vertical Application – NEXT

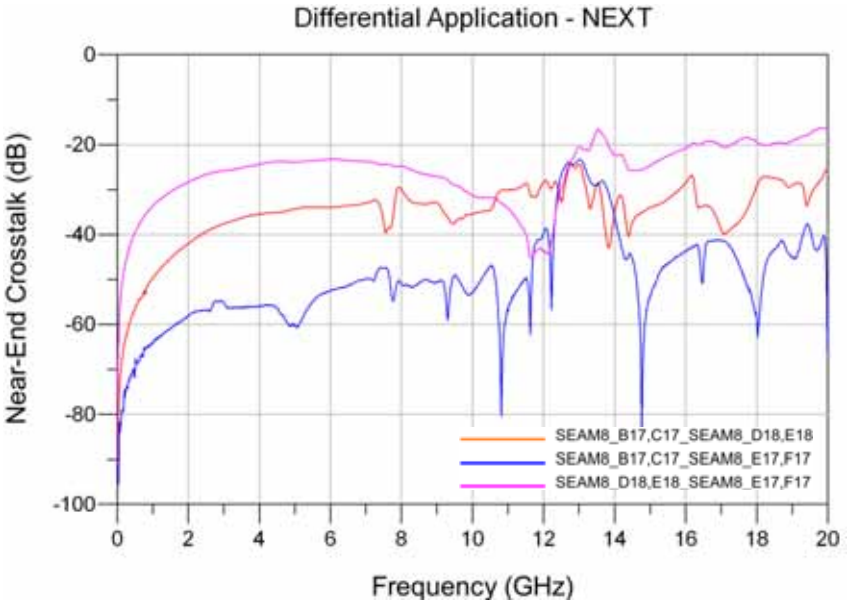


Differential Optimal Vertical Application – FEXT

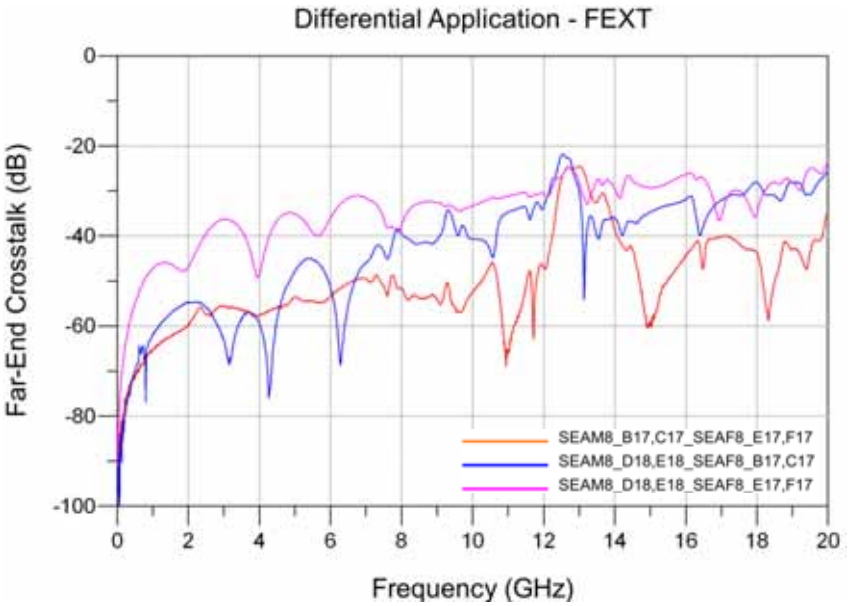


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential High Density Vertical Application – NEXT



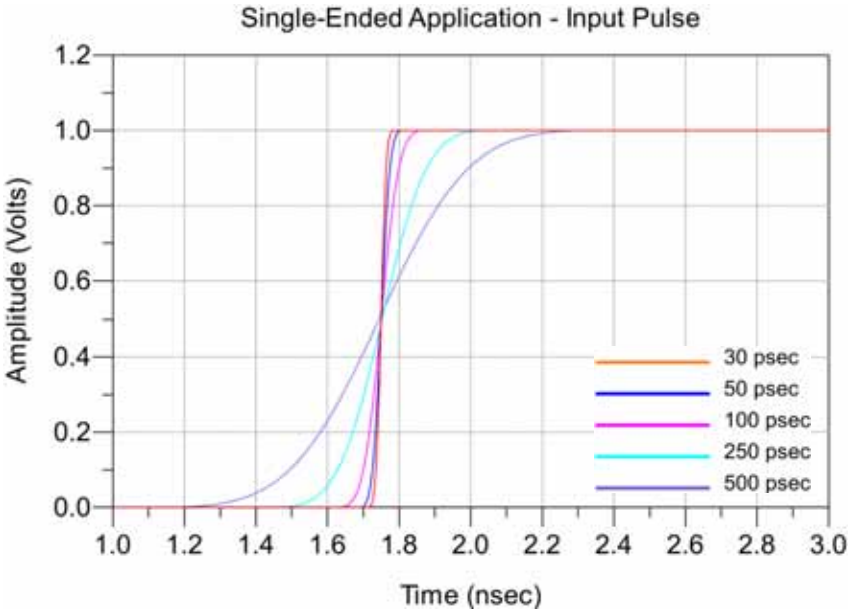
Differential High Density Vertical Application – FEXT



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

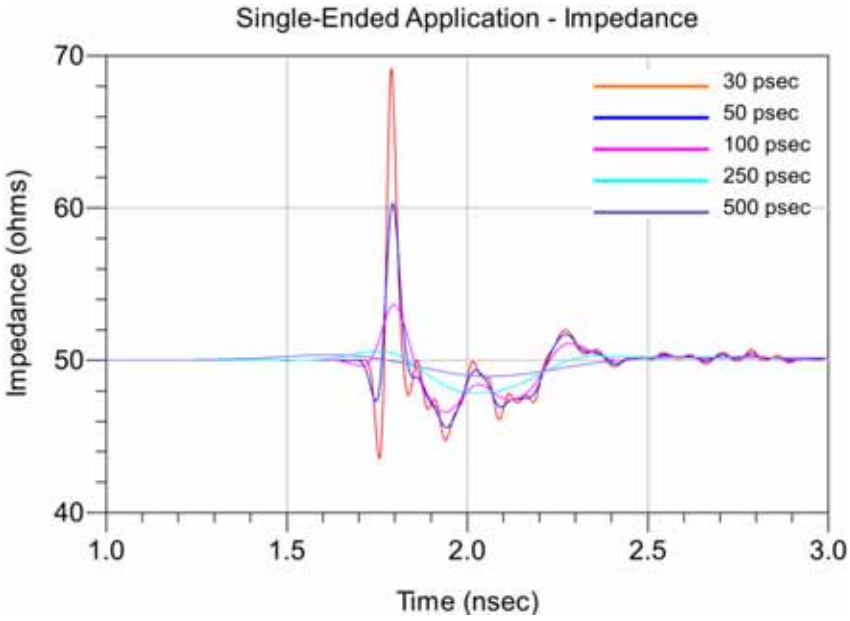
Appendix B – Time Domain Response Graphs

Single-Ended Application – Input Pulse

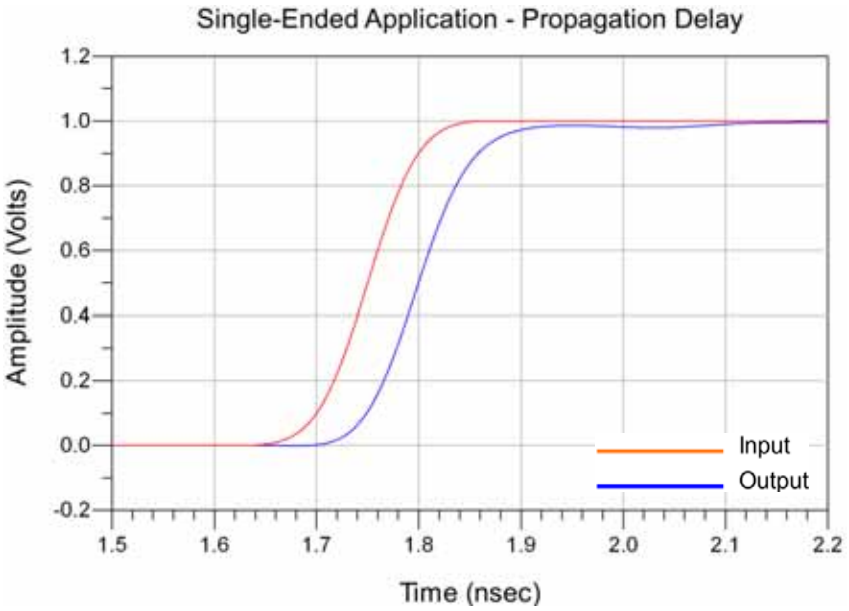


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 1:1 S/G Pattern Application – Impedance

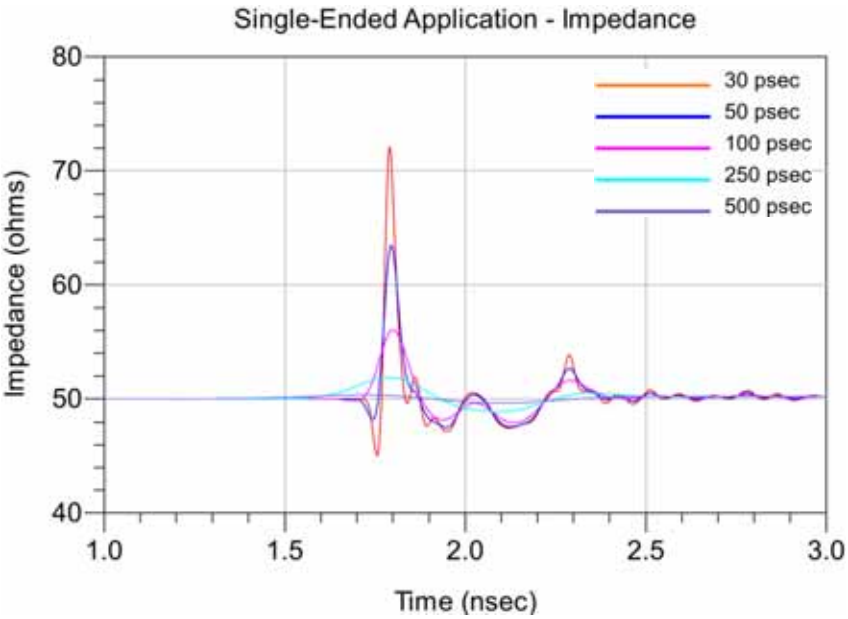


Single-Ended 1:1 S/G Pattern Application – Propagation Delay

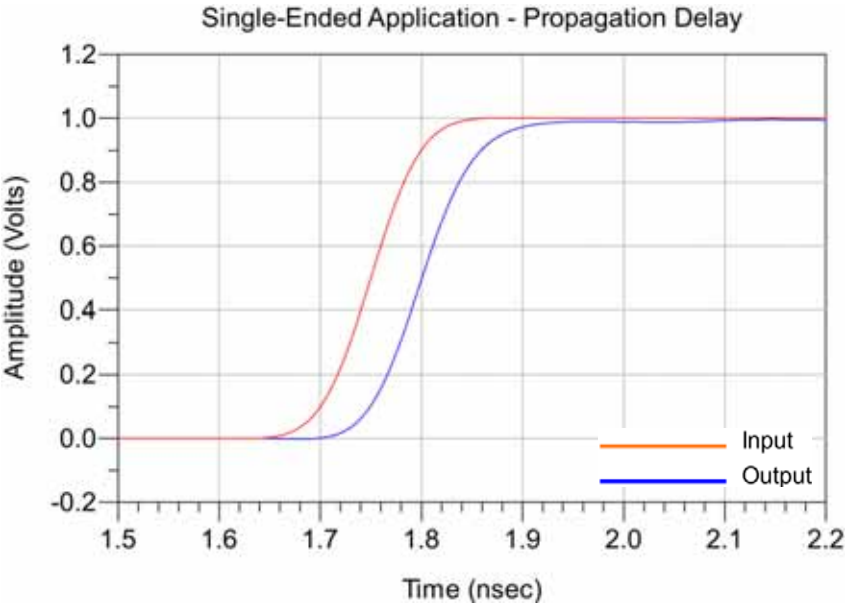


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 2:1 S/G Pattern Application – Impedance

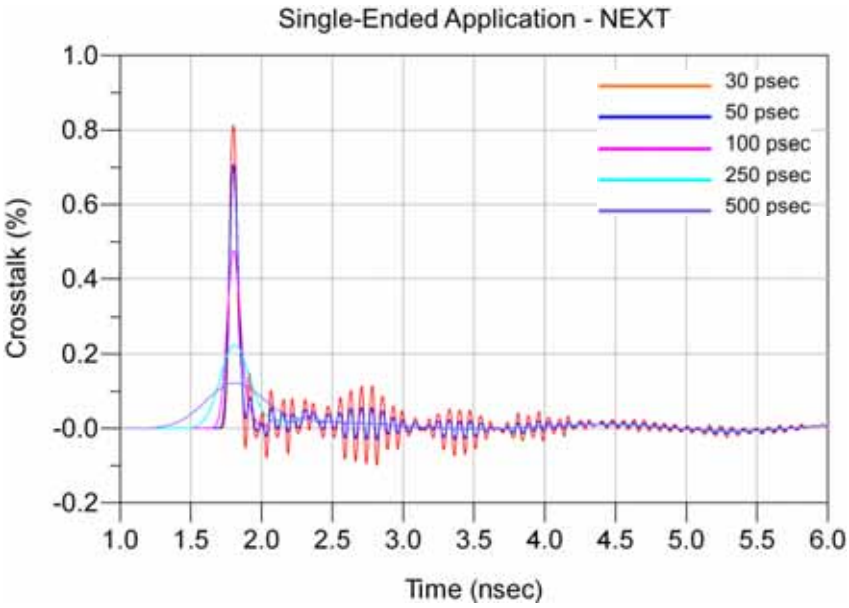


Single-Ended 2:1 S/G Pattern Application – Propagation Delay

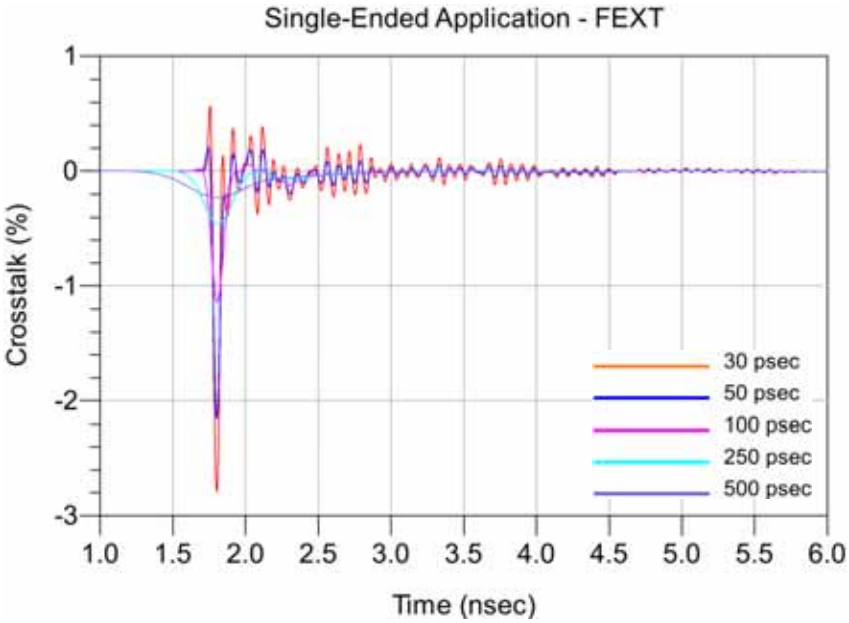


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 1:1 S/G Pattern Application – NEXT, SEAM8_B15_SEAM8_B17

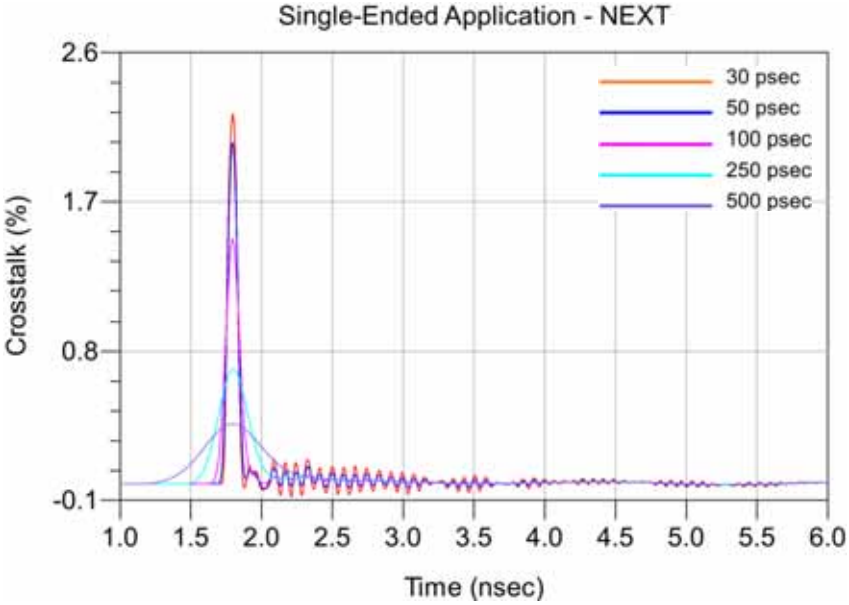


Single-Ended 1:1 S/G Pattern Application – FEXT, SEAM8_C16_SEAF8_B15

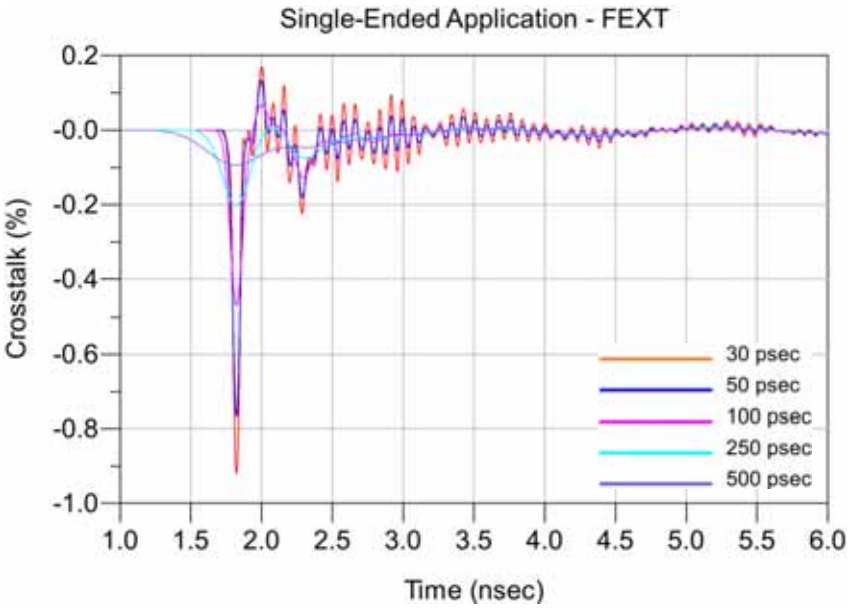


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 1:1 S/G Pattern Application – NEXT, SEAM8_C16_SEAM8_D17

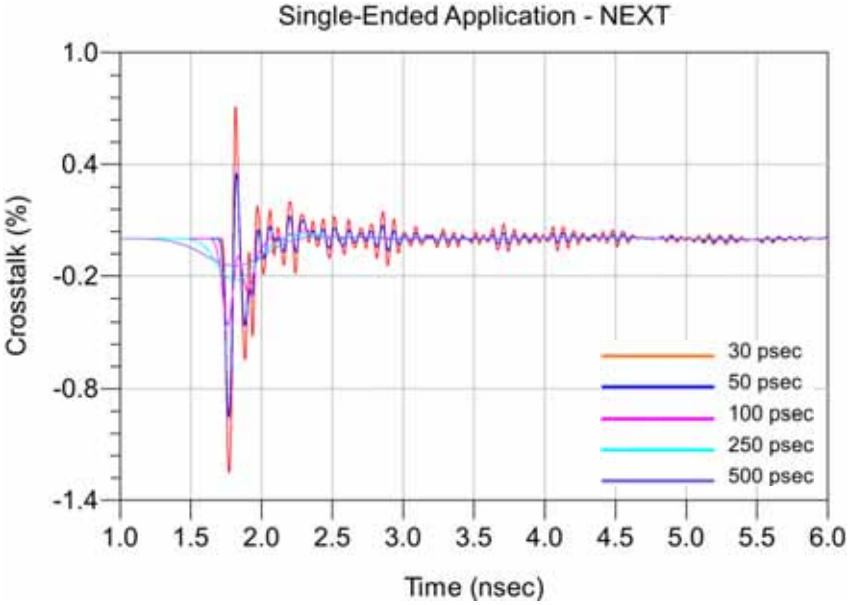


Single-Ended 1:1 S/G Pattern Application – FEXT, SEAM8_C16_SEAF8_D17

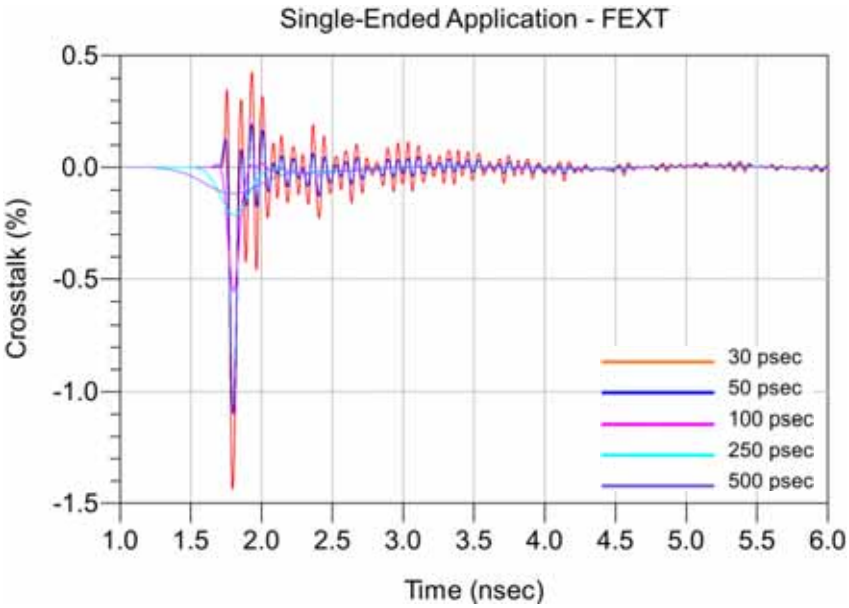


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 1:1 S/G Pattern Application – NEXT, SEAM8_C16_SEAM8_E16

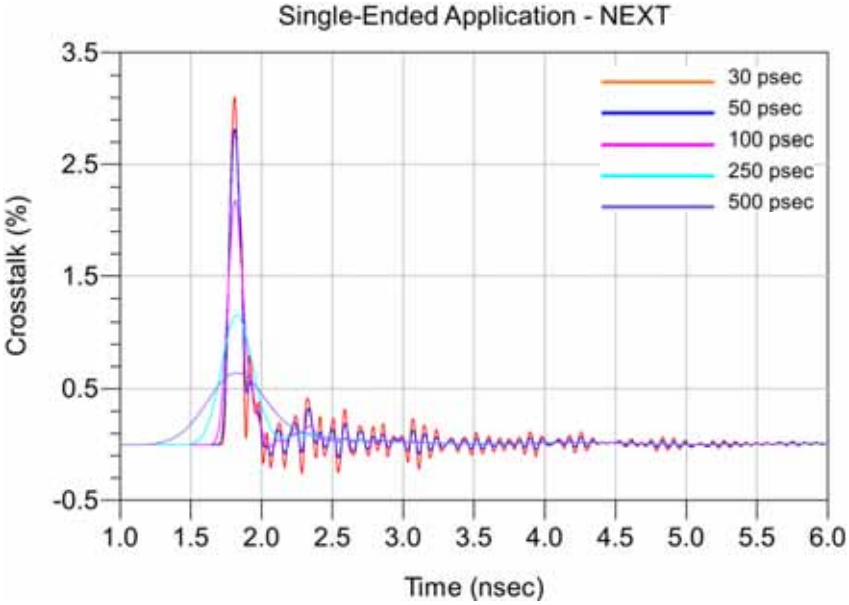


Single-Ended 1:1 S/G Pattern Application – FEXT, SEAM8_C16_SEAF8_E16

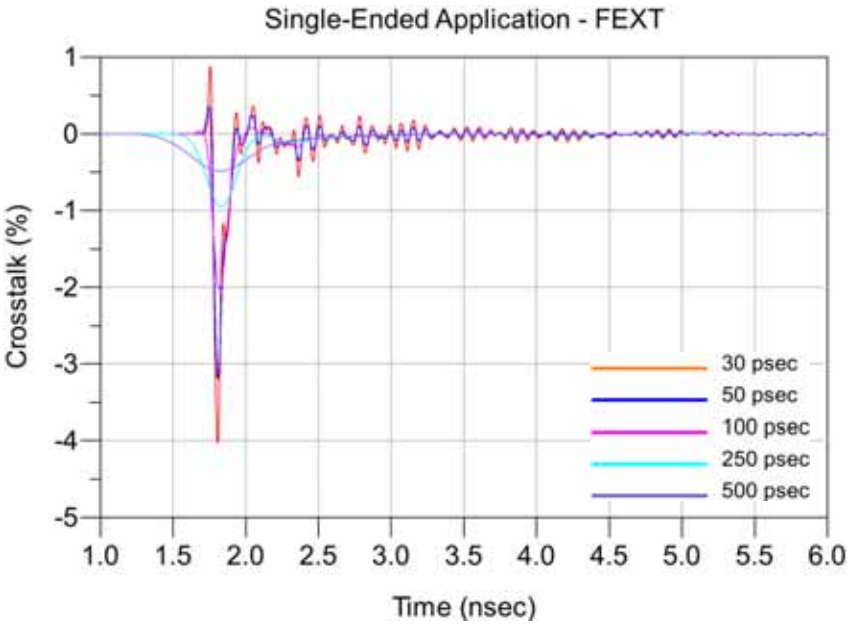


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 2:1 S/G Pattern Application – NEXT, SEAM8_B15_SEAM8_C16

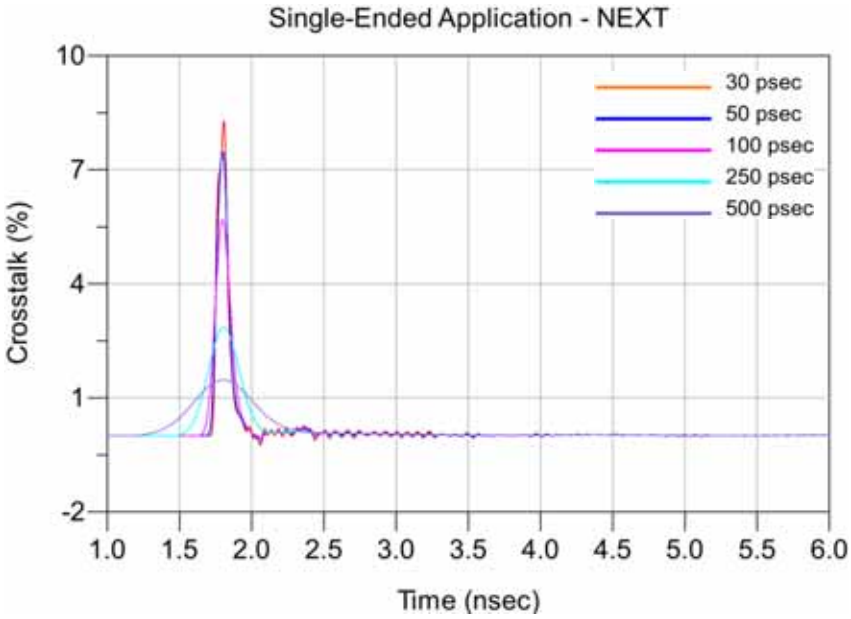


Single-Ended 2:1 S/G Pattern Application – FEXT, SEAM8_C16_SEAF8_B15

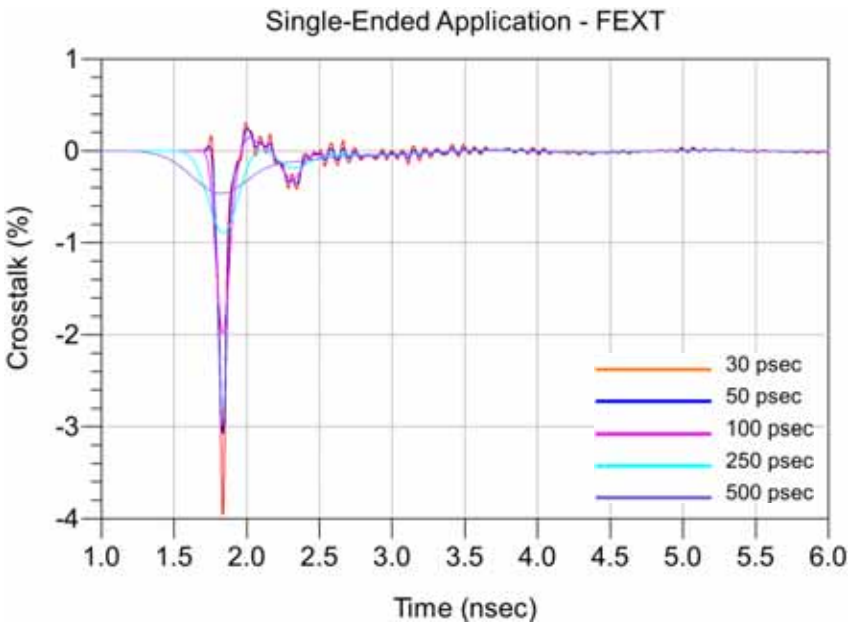


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 2:1 S/G Pattern Application – NEXT, SEAM8_B16_SEAM8_C16

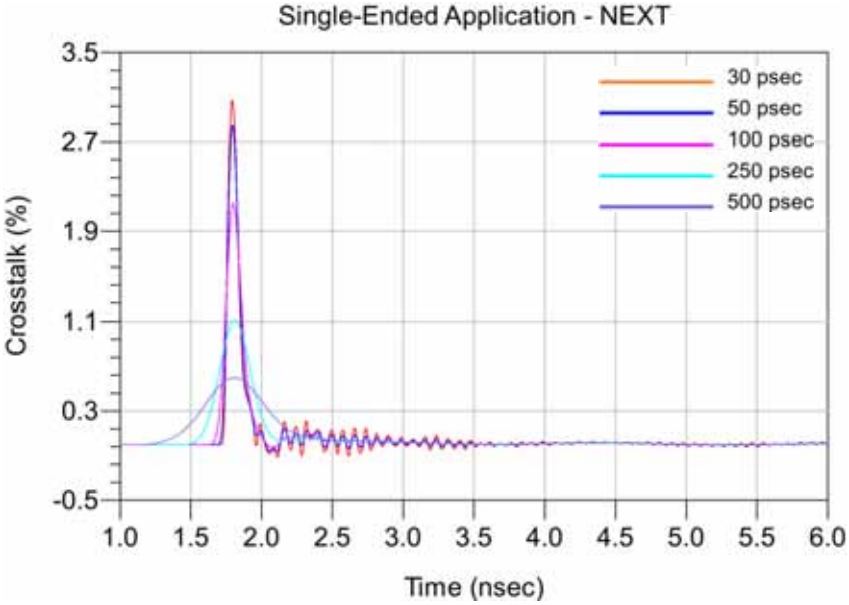


Single-Ended 2:1 S/G Pattern Application – FEXT, SEAM8_C16_SEAF8_B16

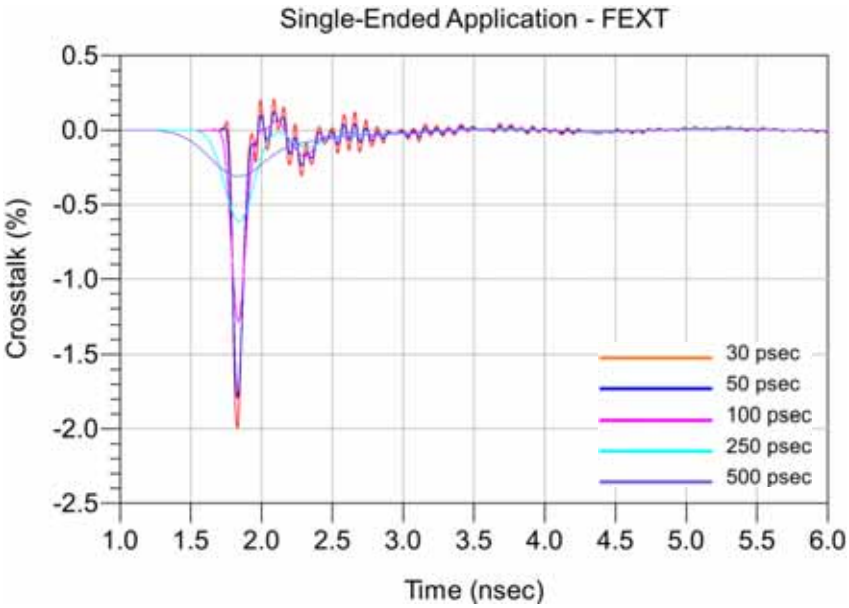


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Single-Ended 2:1 S/G Pattern Application – NEXT, SEAM8_C16_SEAM8_D17

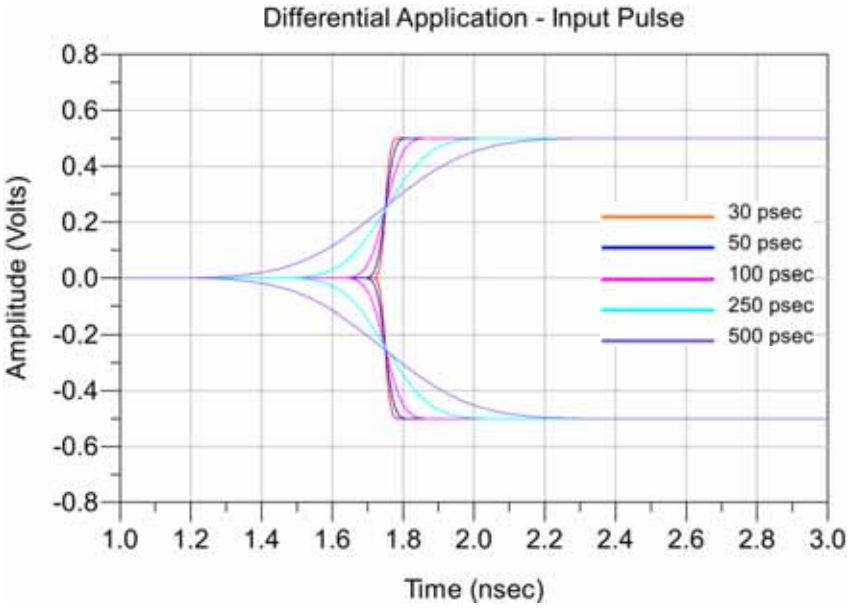


Single-Ended 2:1 S/G Pattern Application – FEXT, SEAM8_C16_SEAF8_D17



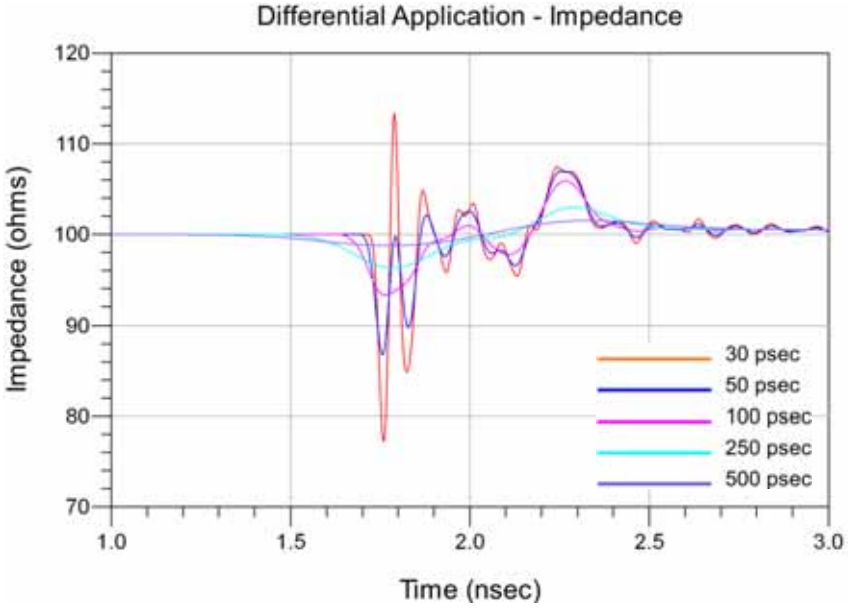
Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential Application – Input Pulse

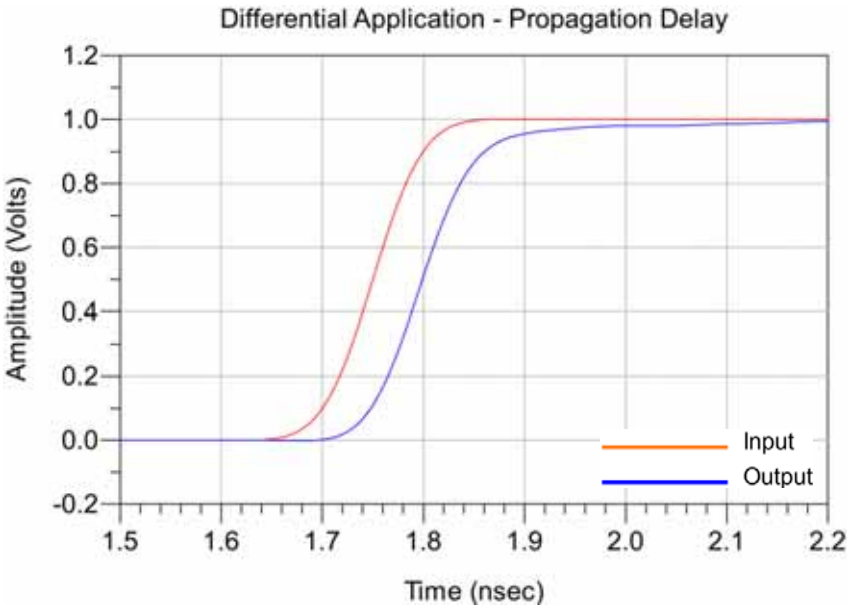


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential Optimal Horizontal Application – Impedance

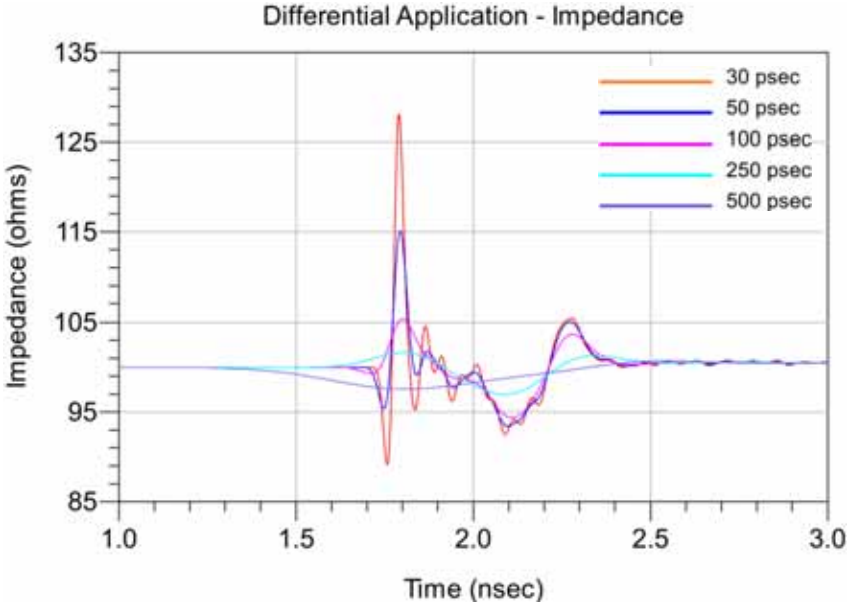


Differential Optimal Horizontal Application – Propagation Delay

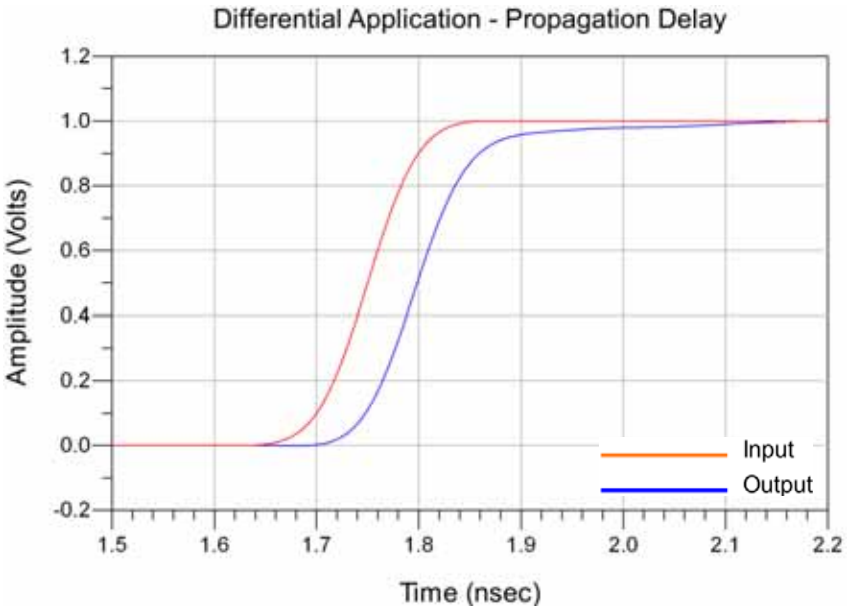


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential Optimal Vertical Application – Impedance

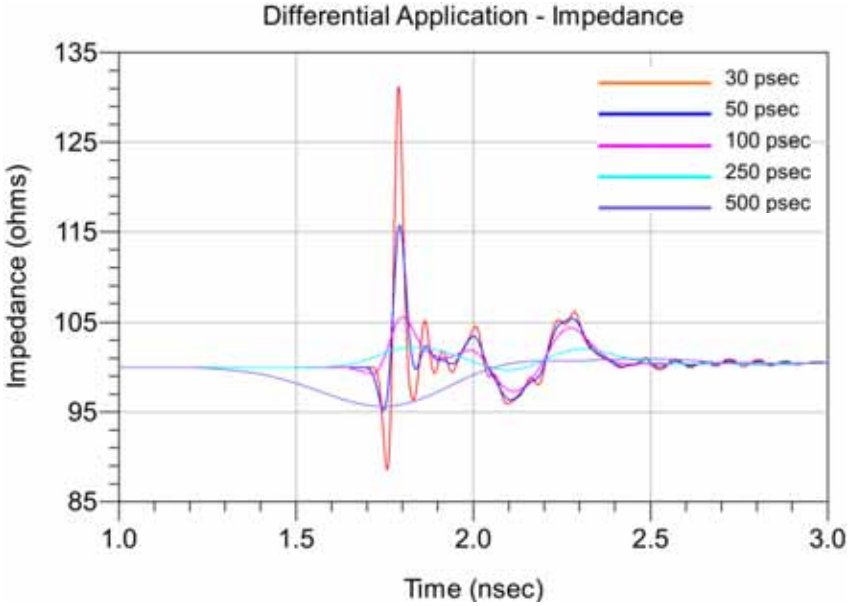


Differential Optimal Vertical Application – Propagation Delay

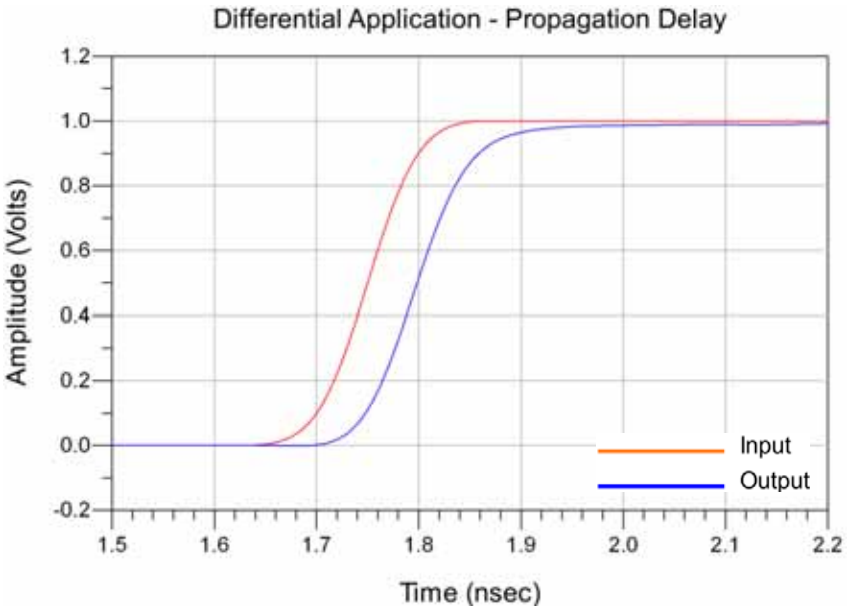


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Differential High Density Vertical Application – Impedance

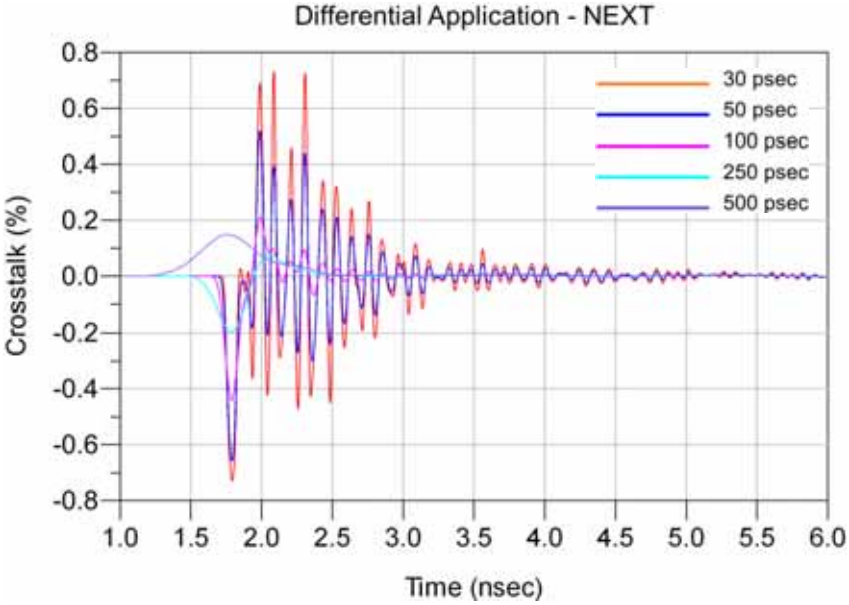


Differential High Density Vertical Application – Propagation Delay

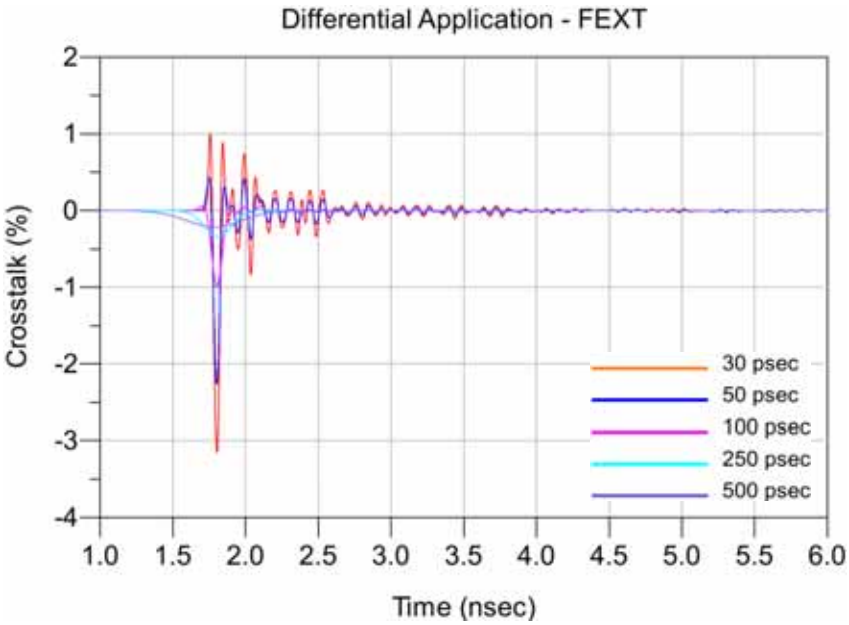


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff Optimal Horizontal Application – NEXT, SEAM8_B13,B14_SEAM8_D13,D14

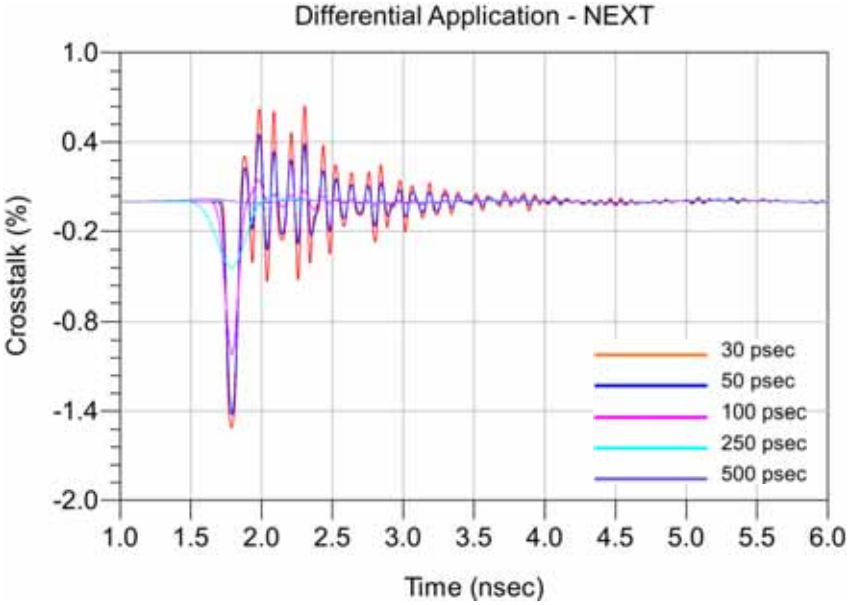


Diff Optimal Horizontal Application – FEXT, SEAM8_D13,D14_SEAF8_B13,B14

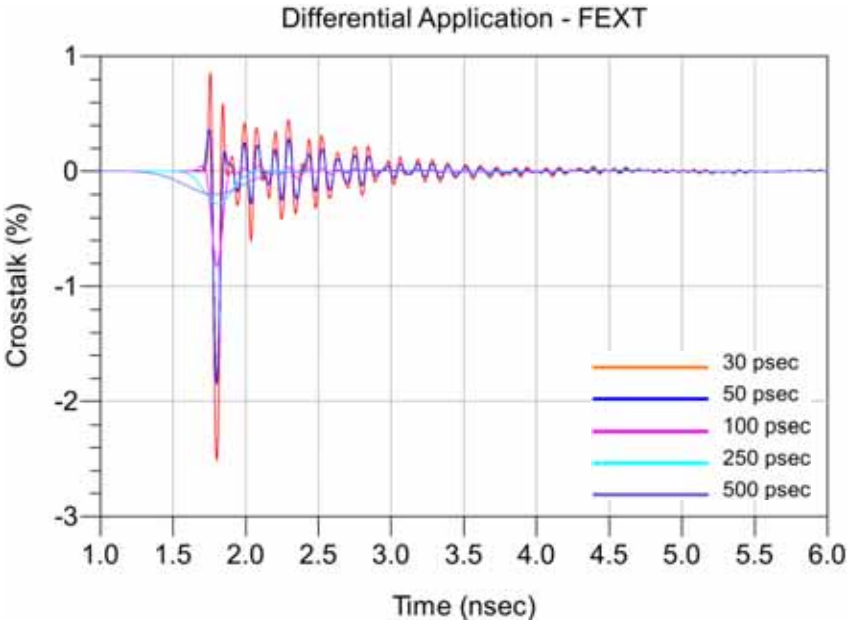


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff Optimal Horizontal Application – NEXT, SEAM8_D13,D14_SEAM8_E15,E16

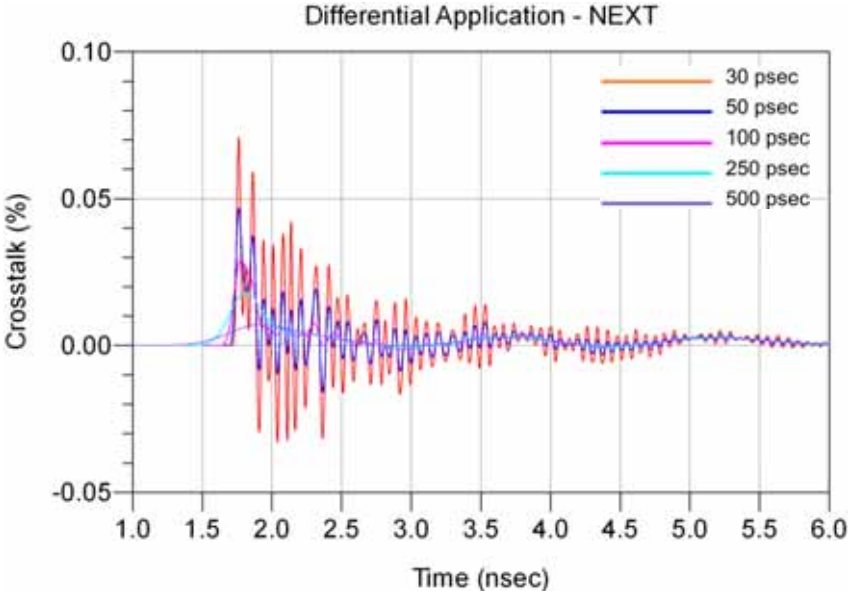


Diff Optimal Horizontal Application – FEXT, SEAM8_D13,D14_SEAF8_E15,E16

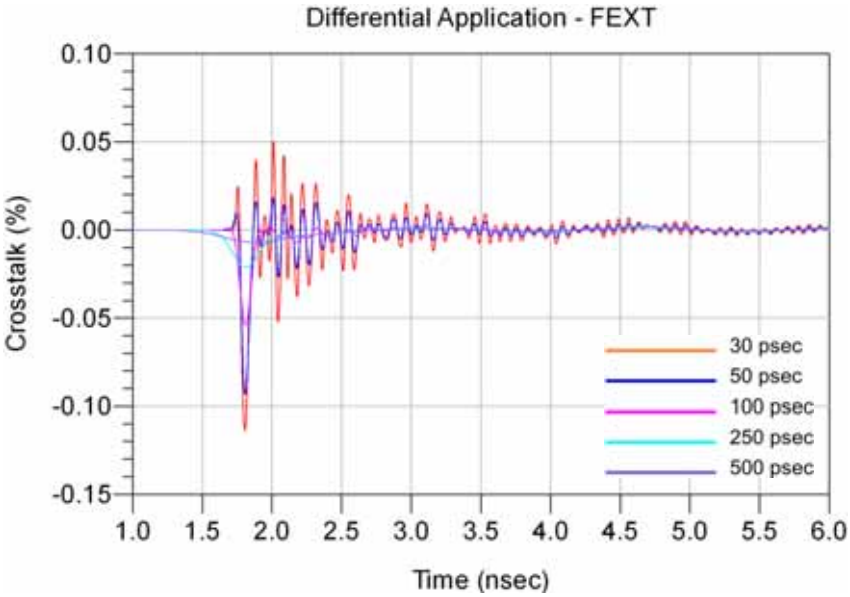


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff Optimal Horizontal Application – NEXT, SEAM8_D13,D14_SEAM8_F13,F14

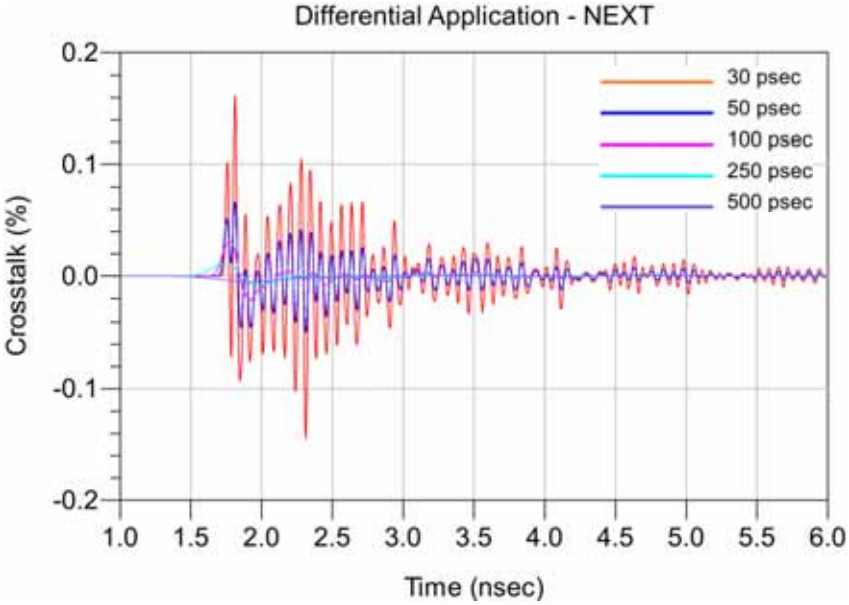


Diff Optimal Horizontal Application – FEXT, SEAM8_D13,D14_SEAF8_F13,F14

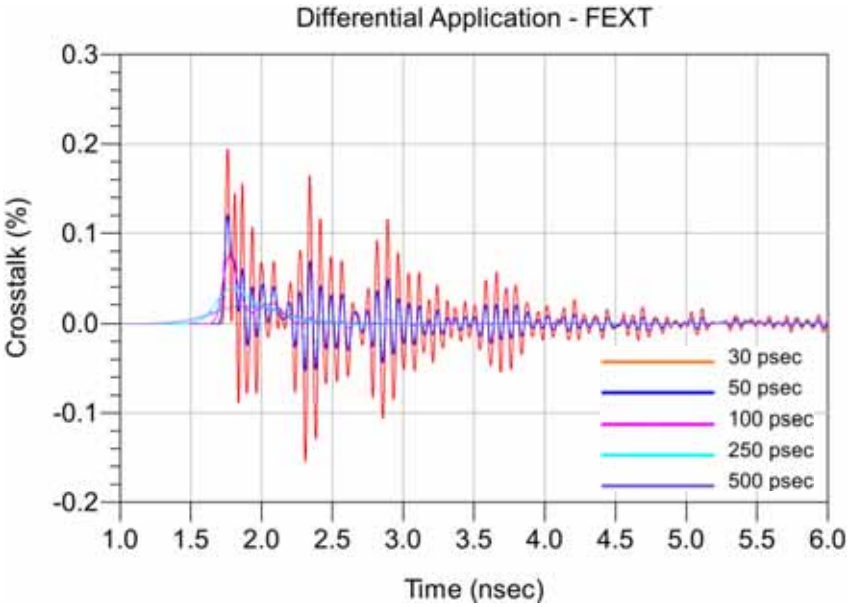


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff Optimal Vertical Application – NEXT, SEAM8_A16,B16_SEAM8_E16,F16

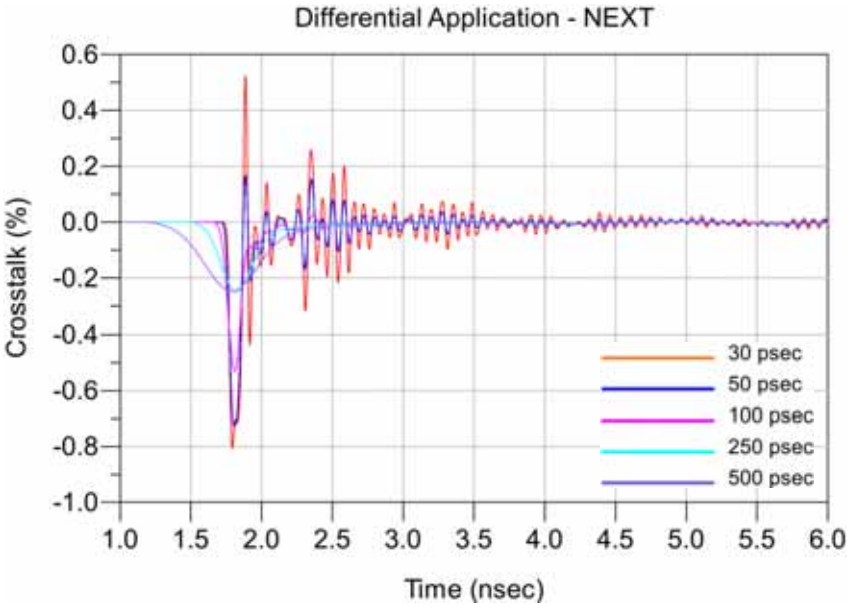


Diff Optimal Vertical Application – FEXT, SEAM8_E16,F16_SEAF8_A16,B16

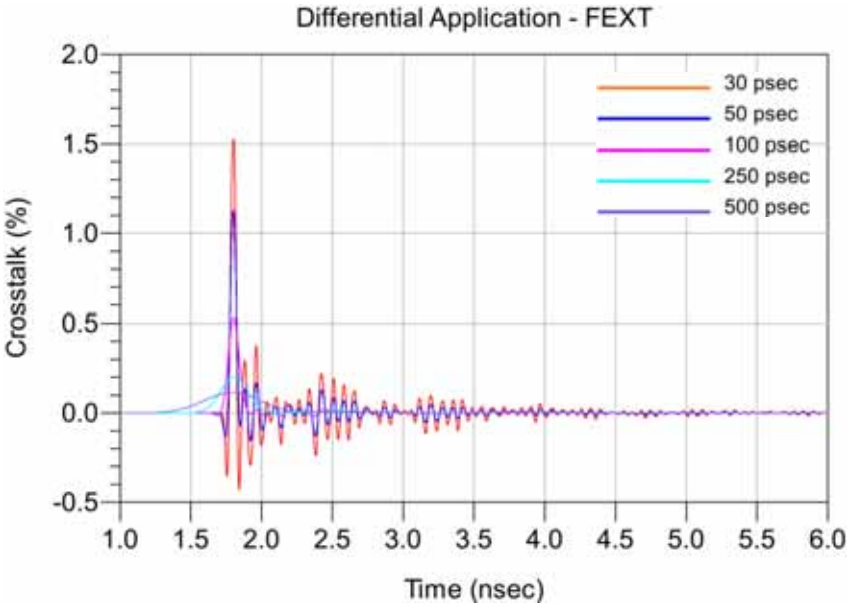


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff Optimal Vertical Application – NEXT, SEAM8_C17,D17_SEAM8_E16,F16

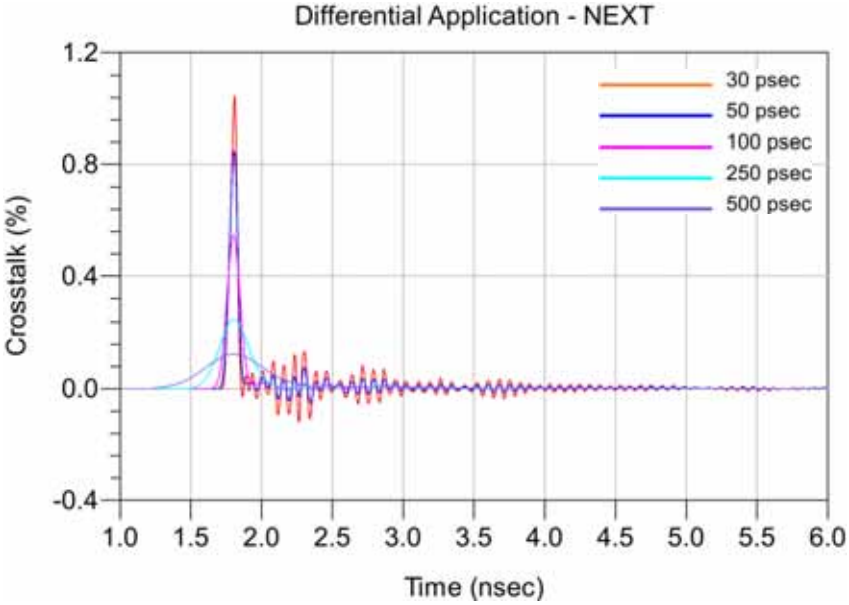


Diff Optimal Vertical Application – FEXT, SEAM8_E16,F16_SEAF8_C17,D17

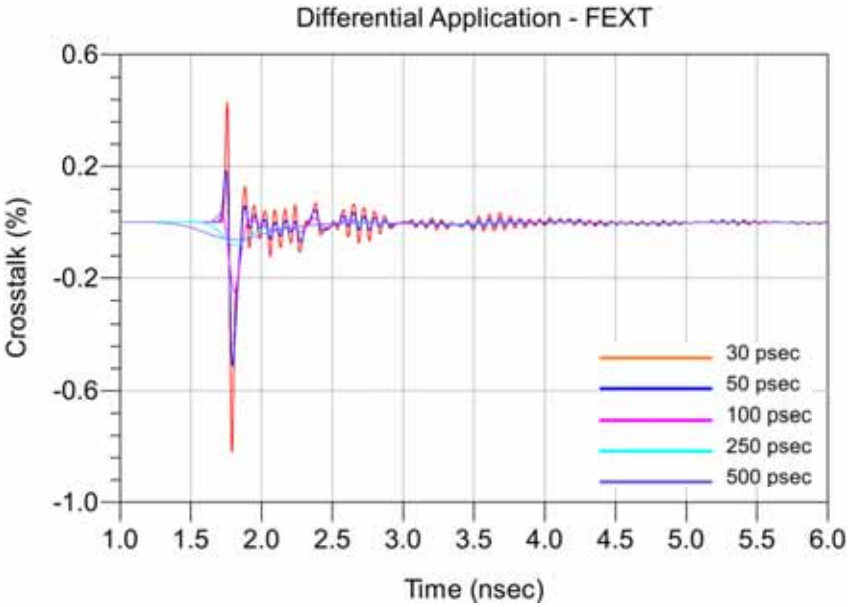


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff Optimal Vertical Application – NEXT, SEAM8_E16,F16_SEAM8_E18,F18

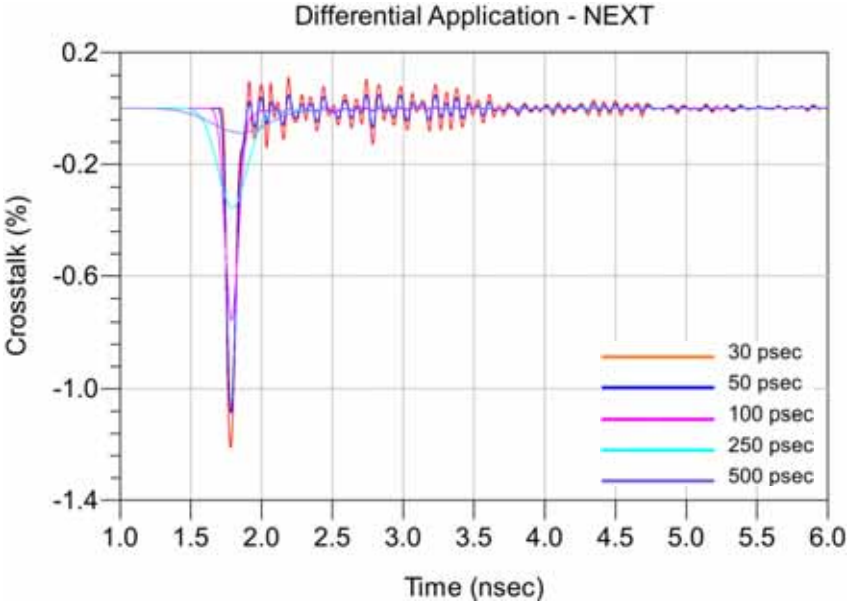


Diff Optimal Vertical Application – FEXT, SEAM8_E16,F16_SEAF8_E18,F18

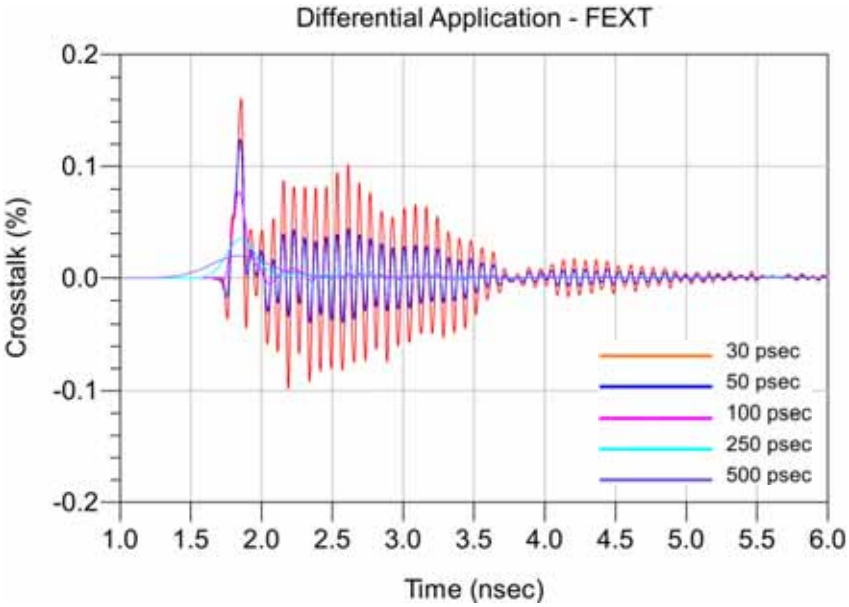


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff High Density Vertical Application – NEXT, SEAM8_B17,C17_SEAM8_D18,E18

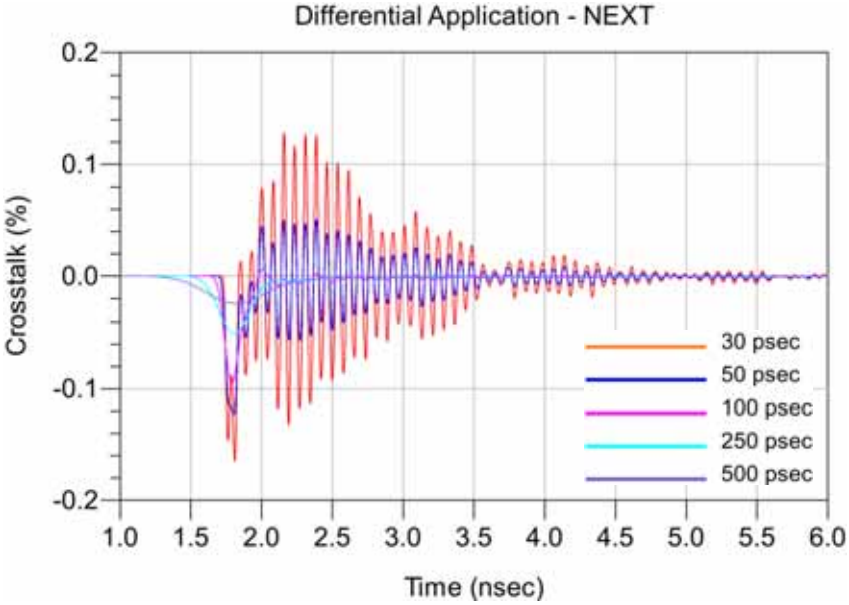


Diff High Density Vertical Application – FEXT, SEAM8_B17,C17_SEAF8_E17,F17

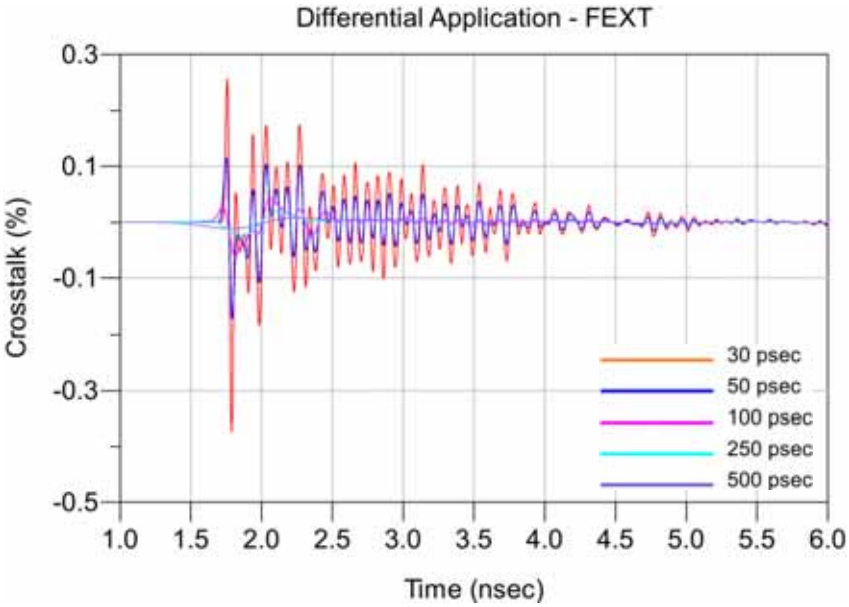


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff High Density Vertical Application – NEXT, SEAM8_B17,C17_SEAM8_E17,F17

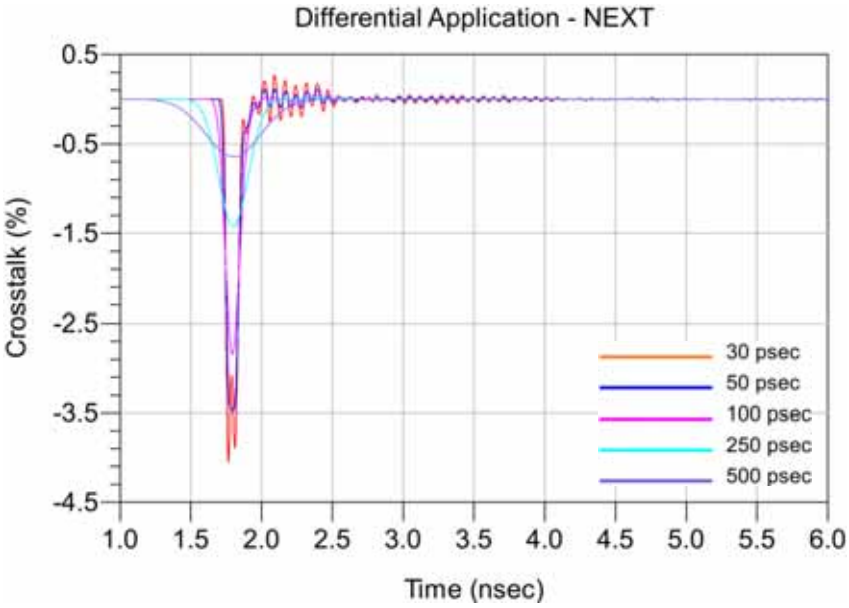


Diff High Density Vertical Application – FEXT, SEAM8_D18,E18_SEAF8_B17,C17

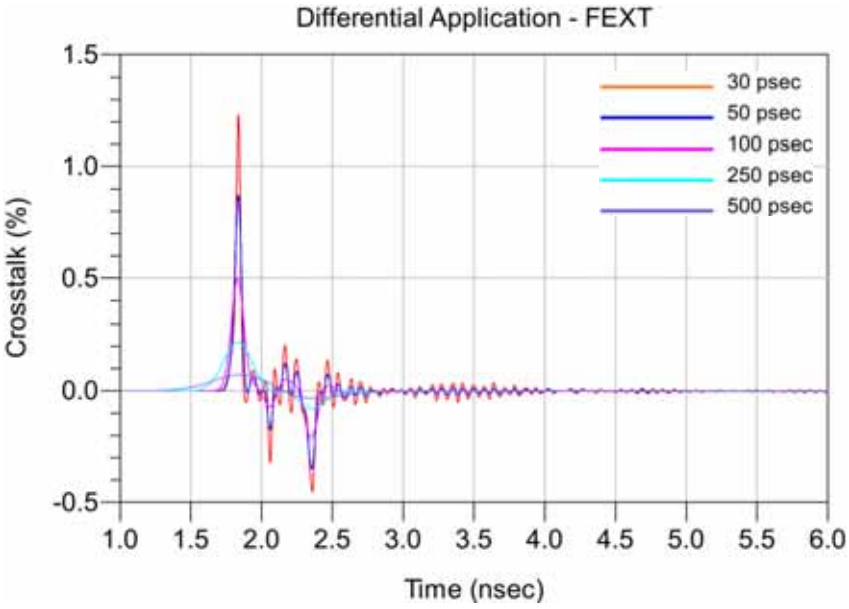


Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Diff High Density Vertical Application – NEXT, SEAM8_D18,E18_SEAM8_E17,F17



Diff High Density Vertical Application – FEXT, SEAM8_D18,E18_SEAF8_E17,F17



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Appendix C – Product and Test System Descriptions

Product Description

Product test samples are 7mm (0.276") stack height SEAM8/SEAF8 Series connectors. The part numbers are SEAM8-30-S02.0-S-06-2-K-TR and SEAF8-30-05.0-S-06-2-K-TR. The SEAM8/SEAF8 Series is an open pin field connector designed for single-ended signals with various options for differential signaling configurations. The open pin field array is 6 rows; with 30 signal pins per row. The space of row centerlines is 0.8mm or 1.2mm alternately. A photo of the test articles mounted to SI test boards is shown below.

Test System Description

The test fixtures are composed of four-layer FR4 material with 50Ω signal trace and pad configurations designed for the electrical characterization of Samtec high speed connector products. A PCB mount SMA connector is used to interface the VNA test cables to the test fixtures. Optimization of the SMA launch was performed using full wave simulation tools to minimize reflections. Eighteen test fixtures are specific to the SEAM8/SEAF8 Series connector set and identified by part numbers PCB-104084-TST-01-A and B to PCB-104084-TST-09 A and B. Calibration standards specific to the SEAM8/SEAF8 Series are located on the calibration board PCB-104084-TST-12. To keep trace lengths short, nine different test board sets were required to access the necessary signal pins.

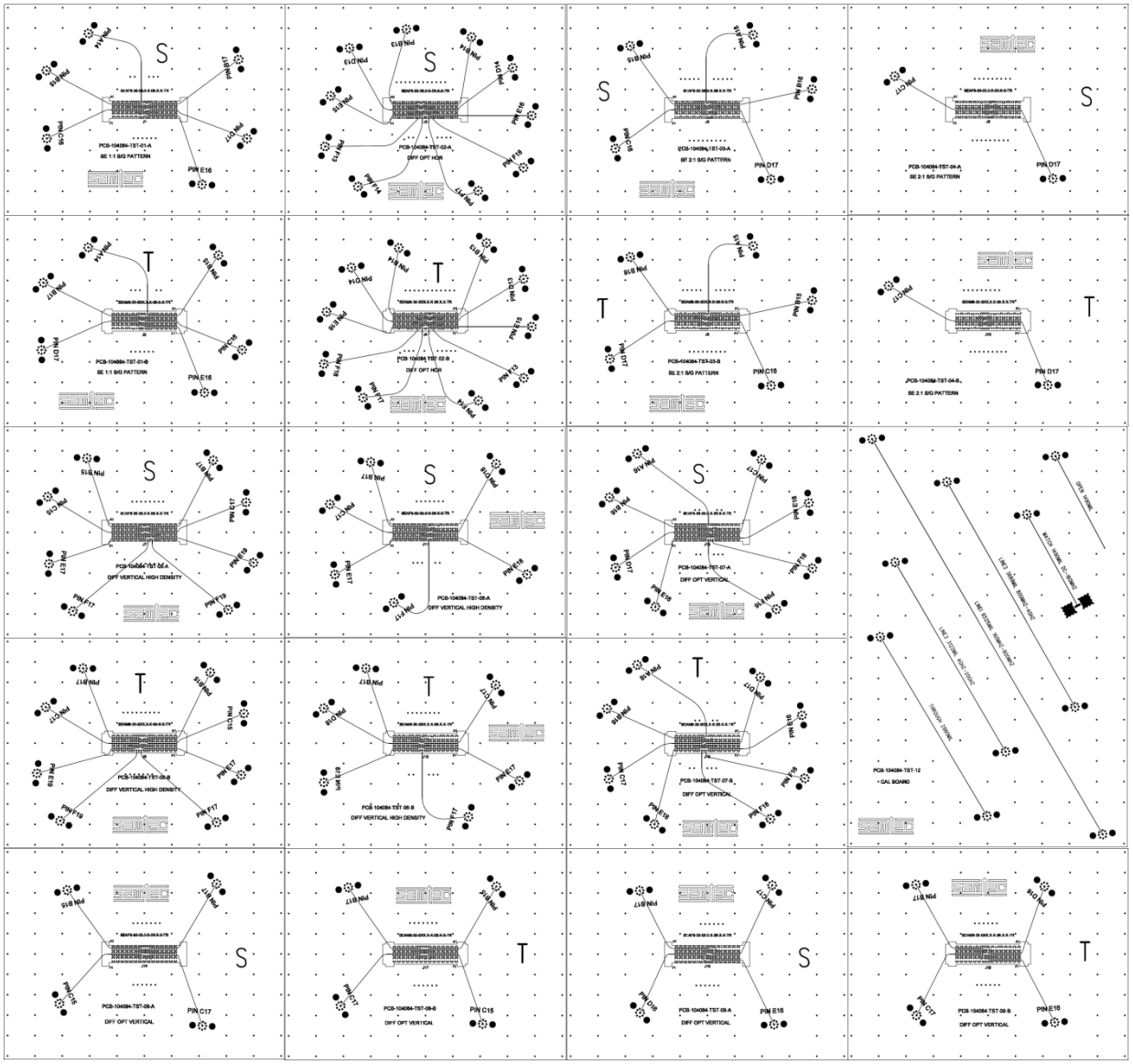
PCB-104084-TST-XX Test Fixtures

Shown below is a photograph of one of the nine test board sets.

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

PCB-104084-TST-XX PCB Layout Panel

Artwork of the PCB design is shown below.



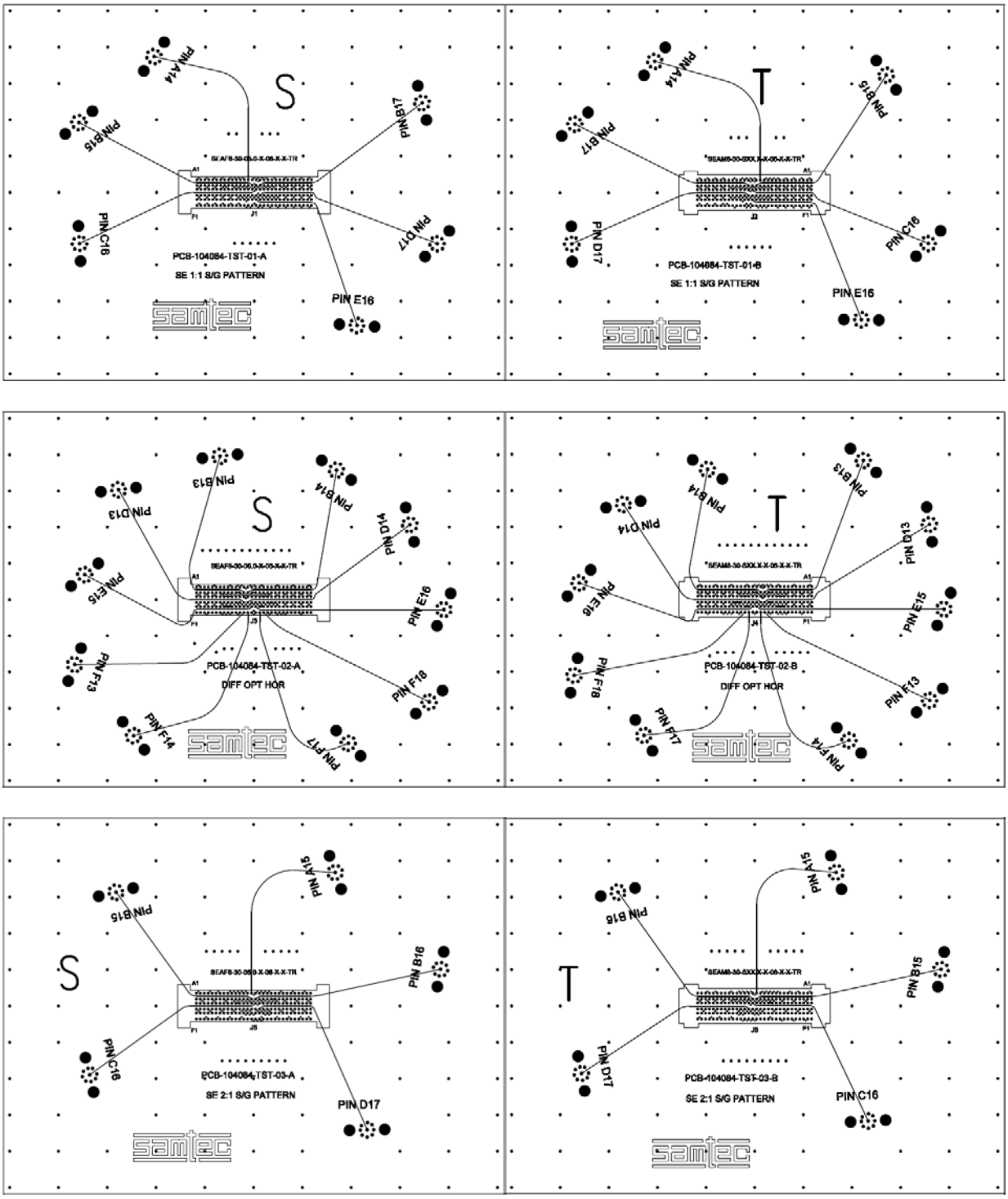
Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

PCB Fixtures

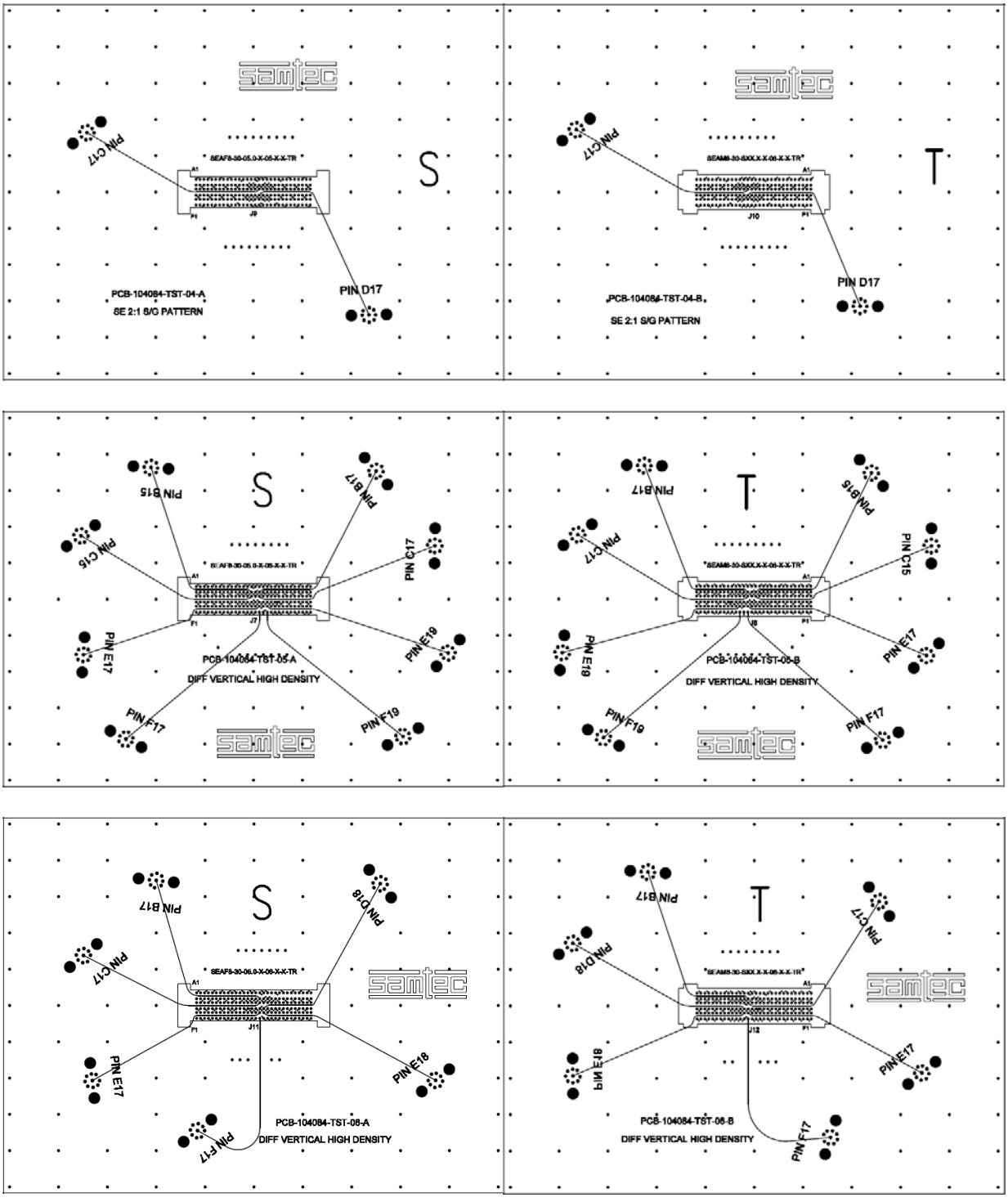
The test fixtures used are as follows:

PCB-104084 -TST-01-A – SEAF8 Series Test Board for SE 1:1 S/G Pattern.
PCB-104084 -TST-01-B – SEAM8 Series Test Board for SE 1:1 S/G Pattern.
PCB-104084 -TST-02-A – SEAF8 Series Test Board for Differential Optimal Horizontal
PCB-104084 -TST-02-B – SEAM8 Series Test Board for Differential Optimal Horizontal
PCB-104084 -TST-03-A – SEAF8 Series Test Board for SE 2:1 S/G Pattern
PCB-104084 -TST-03-B – SEAM8 Series Test Board for SE 2:1 S/G Pattern
PCB-104084 -TST-04-A – SEAF8 Series Test Board for SE 2:1 S/G Pattern
PCB-104084 -TST-04-B – SEAM8 Series Test Board for SE 2:1 S/G Pattern
PCB-104084 -TST-05-A – SEAF8 Series Test Board for Differential High Density Vertical
PCB-104084 -TST-05-B – SEAM8 Series Test Board for Differential High Density Vertical
PCB-104084 -TST-06-A – SEAF8 Series Test Board for Differential High Density Vertical
PCB-104084 -TST-06-B – SEAM8 Series Test Board for Differential High Density Vertical
PCB-104084 -TST-07-A – SEAF8 Series Test Board for Differential Optimal Vertical
PCB-104084 -TST-07-B – SEAM8 Series Test Board for Differential Optimal Vertical
PCB-104084 -TST-08-A – SEAF8 Series Test Board for Differential Optimal Vertical
PCB-104084 -TST-08-B – SEAM8 Series Test Board for Differential Optimal Vertical
PCB-104084 -TST-09-A – SEAF8 Series Test Board for Differential Optimal Vertical
PCB-104084 -TST-09-B – SEAM8 Series Test Board for Differential Optimal Vertical

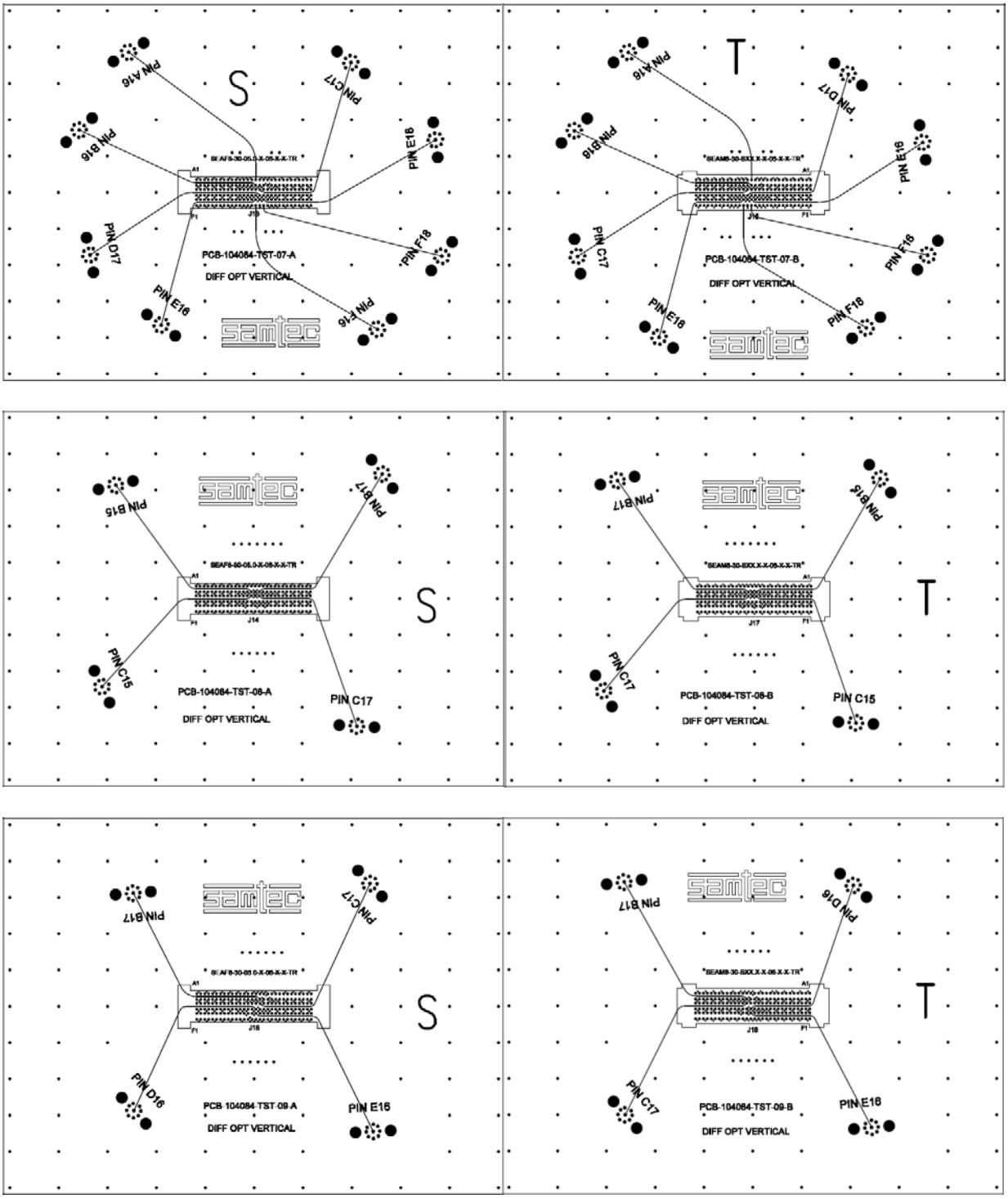
Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height



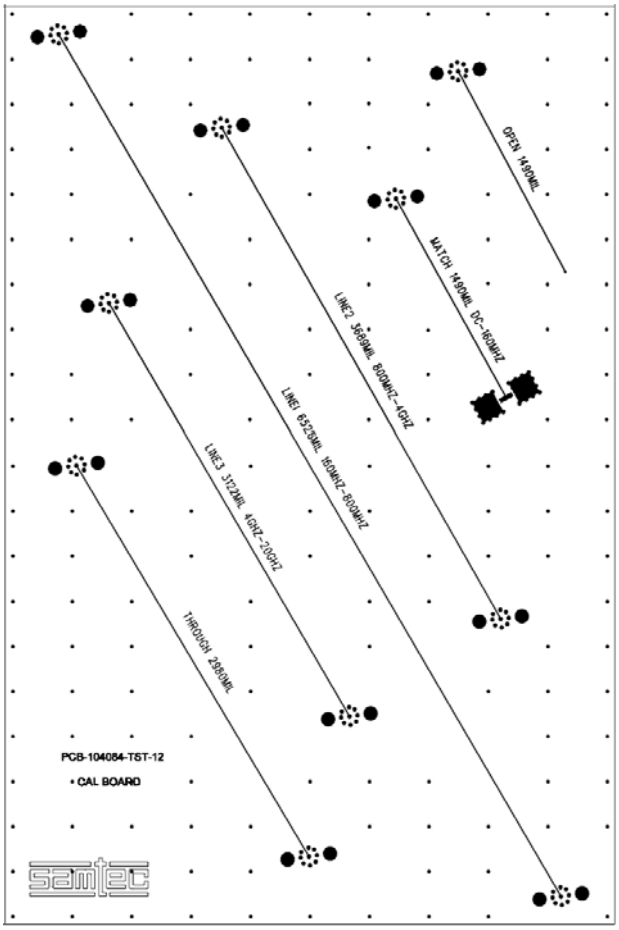
Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Calibration Board

Test fixture losses and test point reflections were removed from the data by use of TRL calibration. The calibration board is shown below. Prior to making any measurements, the calibration board is characterized to obtain parameters required to define the calibration kit. Once a cal kit is defined, calibration using the standards on the calibration board can be performed. Finally, the device can be measured and the test board effects are automatically removed.



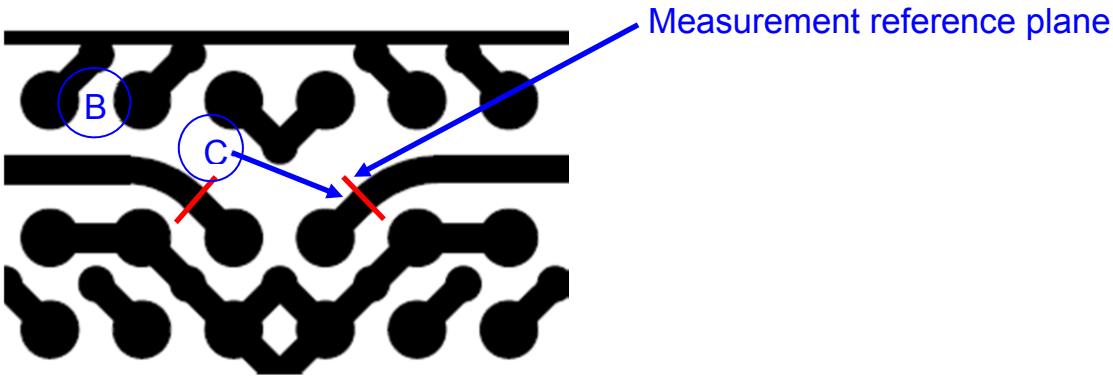
Thru line – 2980 mils
Open Reflect – 1490 mils
Line 1 – 6526 mils
Line 2 – 3689 mils
Line 3 – 3122 mils
Match – 1490 mils

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

All traces on the test boards are length matched to 1.5" measured from the edge of the pad to the SMA. The TRL calibration effectively removes 1.490" of test board trace effects. This means that 10 mils of test board trace length effects are included in the measurement. The S-Parameter measurement includes:

A- The SEAM8/SEAF8 Series connector set
B- Test board vias, pads (footprint effects)
C- 10 mils of 9.5 mil wide microstrip trace

The figure below shows the location of the measurement reference plane.



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

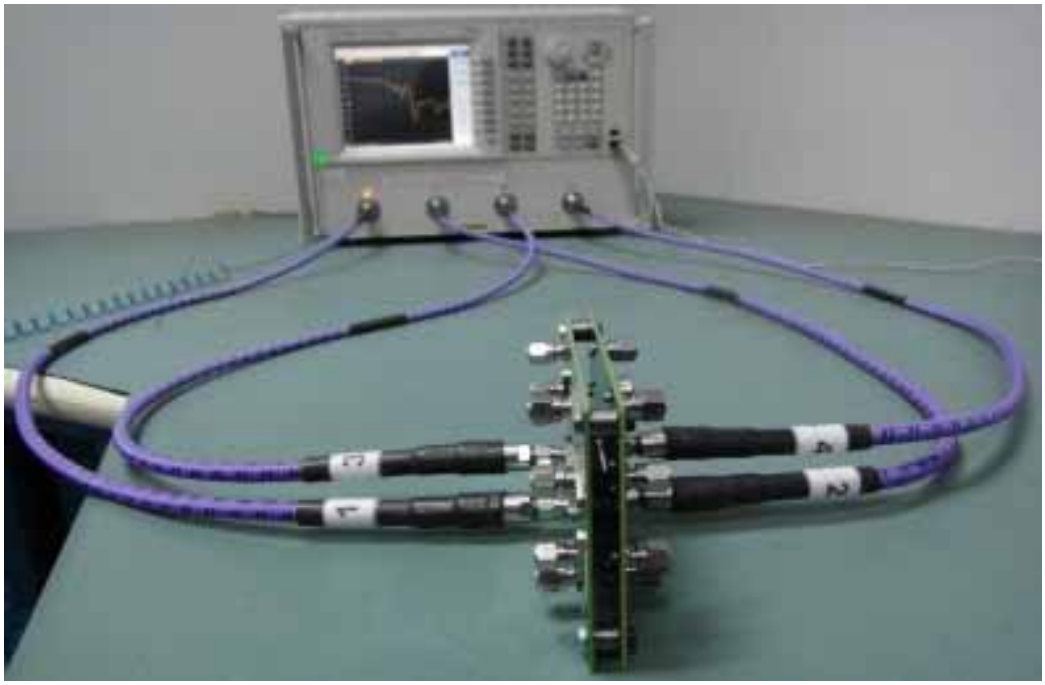
Appendix D – Test and Measurement Setup

The test instrument is the Agilent N5230C PNA-L network analyzer. Frequency domain data and graphs are obtained directly from the instrument. Post-processed time domain data and graphs are generated using convolution algorithms within Agilent ADS. The network analyzer is configured as follows:

Start Frequency – 300 KHz
Stop Frequency – 20 GHz
Number of points -1601
IFBW – 1 KHz

With these settings, the measurement time is approximately 20 seconds.

N5230C Measurement Setup



Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Test Instruments

QTY	Description
1	Agilent N5230C PNA-L Network Analyzer (300 KHz to 20 GHz)
1	Agilent N4433A ecal module (300 KHz to 20 GHz)

Test Cables & Adapters

QTY	Description
4	Gore OWD01D02039-4 (DC-50 GHz)

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Appendix E - Frequency and Time Domain Measurements

Frequency (S-Parameter) Domain Procedures

The quality of any data taken with a network analyzer is directly related to the quality of the calibration standards and the use of proper test procedures. For this reason, extreme care is taken in the design of the LRM calibration standards, the SI test boards, and the selection of the PCB vendor.

The measurement process begins with a measurement of the LRM calibration standards. A coaxial SOLT calibration is performed using an N4433A ecal module. This measurement is required in order to obtain precise values of the line standard offset delay and frequency bandwidths. Measurements of the reflect and 2x through line standard can be used to determine the maximum frequency for which the calibration standards are valid. For the SEAM8/SEAF8 Series test boards, this is greater than 20 GHz.

From the LRM calibration standard measurements, a user defined calibration kit is developed and stored in the network analyzer. Calibration is then performed on all 4 ports following the calibration wizard within the Agilent N5230C. This calibration is saved and can be recalled at any time. Calibration takes roughly 30 minutes to perform.

Time Domain Procedures

Mathematically, Frequency Domain data can be transformed to obtain a Time Domain response. Perfect transformation requires Frequency Domain data from DC to infinity Hz. Fortunately, a very accurate Time Domain response can be obtained with bandwidth-limited data, such as measured with modern network analyzer.

The Time Domain responses were generated using Agilent ADS 2009 update 1. This tool has a transient convolution simulator, which can generate a Time Domain response directly from measured S-Parameters. An example of a similar methodology is provided in the Samtec Technical Note on domain transformation.
http://www.samtec.com/Technical_Library/reference/articles/pdfs/tech-note_using-PLTS-for-time-domain-data_web.pdf

Impedance (TDR)
A step pulse is applied to the touchstone model of the connector and the reflected voltage is monitored. The reflected voltage is converted to a reflection coefficient and then transformed into an impedance profile. All ports of the Touchstone model are terminated in 50 ohms.

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Propagation Delay (TDT)

The Propagation Delay is a measure of the Time Domain delay through the connector and footprint. A step pulse is applied to the touchstone model of the connector and the transmitted voltage is monitored. The same pulse is also applied to a reference channel with zero loss, and the Time Domain pulses are plotted on the same graph. The difference in time, measured at the 50% point of the step voltage is the propagation delay.

Near-End Crosstalk (TDT) & Far End Crosstalk (TDT)

A step pulse is applied to the touchstone model of the connector and the coupled voltage is monitored. The amplitude of the peak-coupled voltage is recorded and reported as a percentage of the input pulse.

Series: SEAM8/SEAF8
Description: Open Pin Field Array, 0.8mm Pitch, 7mm Stack Height

Appendix F – Glossary of Terms

ADS – Advanced Design Systems
BC – Best Case crosstalk configuration
DUT – Device under test, term used for TDA IConnect & Propagation Delay waveforms
FD – Frequency domain
FEXT – Far-End Crosstalk
GSG – Ground–Signal-Ground; geometric configuration
GSSG - Ground–Signal-Signal-Ground; geometric configuration
HDV – High Density Vertical
NEXT – Near-End Crosstalk
OV – Optimal Vertical
OH – Optimal Horizontal
PCB – Printed Circuit Board
PPO – Pin Population Option
SE – Single-Ended
SI – Signal Integrity
SUT – System Under Test
S – Static (independent of PCB ground)
SOLT – acronym used to define Short, Open, Load & Thru Calibration Standards
TD – Time Domain
TDA – Time Domain Analysis
TDR – Time Domain Reflectometry
TDT – Time Domain Transmission
WC – Worst Case crosstalk configuration
Z – Impedance (expressed in ohms)